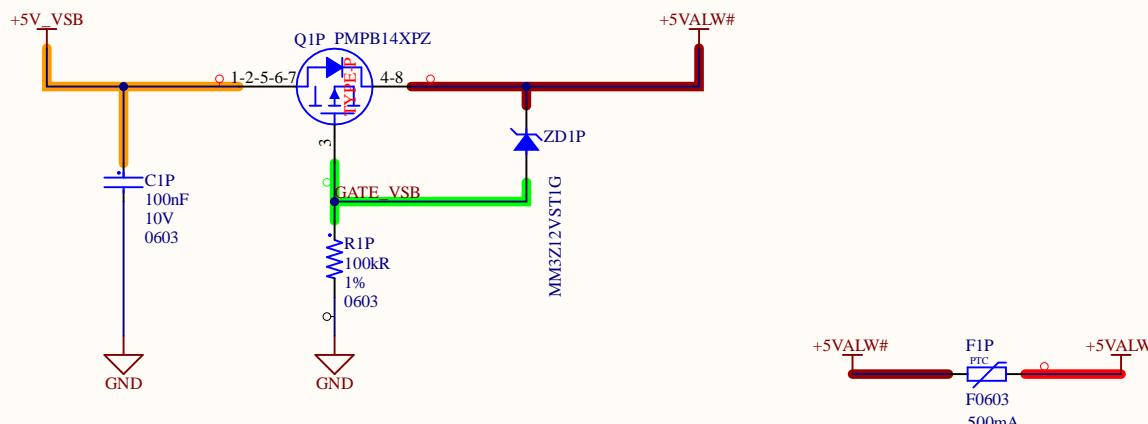
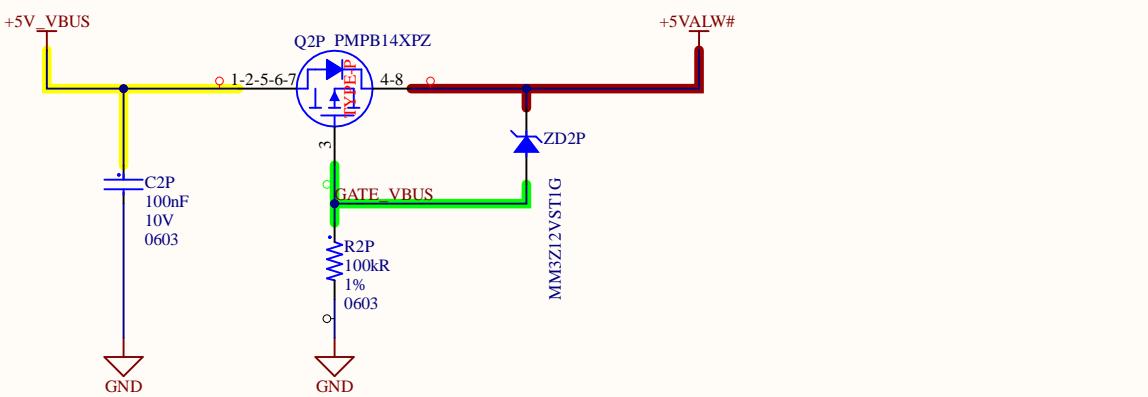


A



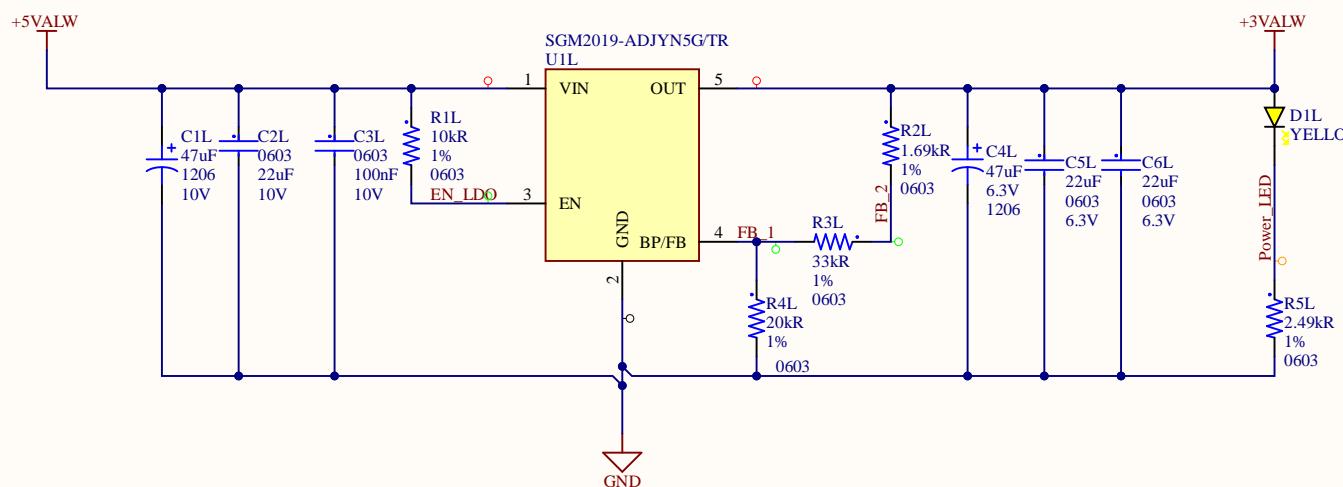
B



C

Title: Power_Path		Author: Alcatraz	DHNLAB PVT LTD DHANBAD JHARKHAND INDIA ASIA
Size: A4 Prj: ESP8266-Desktop_Power		Approved: Alcatraz	
Date: 06-12-2024 20:12:58 Sheet: 1 of 10		Edited: 24-11-2024	
Git Hash: 437		Variant: [No Variations]	
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\1_Power_Path.SchDoc		SW Version: 24.10.1.45	





△ SGM2019-ADJ
Populate R0L, R1L and R2L

SGM2019-3.3
Only Populate R2L With 100nF Cap
DNP - R0L, R1L

HT7833
DNP - R0L, R1L and R2L

△ SGM2019-ADJYN5G/TR

Vout = 3.3V
Register Values For
R0L, R1L and R2L
R1L=R0B+R1L

△ Values From Datasheet

Standard 1% Resistor Values for Common Output Voltages of Adjustable Voltage Version

Vout (V)	R1 (kΩ)	R2 (kΩ)
1.2	0	63.4
1.5	10.5	42.2
1.8	34	63.4
2.8	84.5	63.4
3.0	63.4	42.2
3.3	73.2	42.2
3.6	84.5	42.2
4.2	105	42.2

NOTE: $V_{out} = (R_1 + R_2) / R_2 \times 1.207$

Here are the calculated values of R1L (in kΩ) for VOUT= 3.3 V with different R2L values:
IF R0L= 0Ω
R2L=10kΩ:R1L≈17.34kΩ
R2L=20kΩ:R1L≈34.68kΩ
R2L=30kΩ:R1L≈52.02kΩ
R2L=40kΩ:R1L≈69.36kΩ
R2L=50kΩ:R1L≈86.70kΩ
R2L=60kΩ:R1L≈104.04kΩ
R2L=70kΩ:R1L≈121.38kΩ
R2L=80kΩ:R1L≈138.72kΩ
R2L=90kΩ:R1L≈156.06kΩ
R2L=100kΩ:R1L≈173.41kΩ

Title: LDO	Author: Alcatraz	DHNLAB PVT LTD
Approved: Alcatraz		DHANBAD
Size: A4	Prj: ESP8266-Desktop_Power	JHARKHAND
Date: 06-12-2024 20:12:58	Edited: 06-12-2024	INDIA
Git Hash: 477	Variant: [No Variations]	ASIA
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\2_LDO.SchDoc	SW Version: 24.10.1.45	



PIN NAMES

GPIO16(D0)
GPIO5(D1)=I2C=SCL=_N
GPIO4(D2)=I2C=SDA=_P
GPIO0(D3)
GPIO2(D4)
GPIO14(D5)
GPIO12(D6)
GPIO13(D7)
GPIO15(D8)
GPIO3(RX)= UART0
GPIO1(TX)= UART0
GPIO9(SD2)
GPIO10(SD3)

PIN IS HIGH ON BOOT

D0 = GPIO16
D2 = GPIO4
RX = GPIO3
TX = GPIO1
SD2 = GPIO9
SD3 = GPIO10

BOOT FAILURE IF PULLED LOW

D3 = GPIO0
D2 = GPIO4
TX = GPIO1

BOOT FAILURE IF PULLED HIGH

D8 = GPIO15

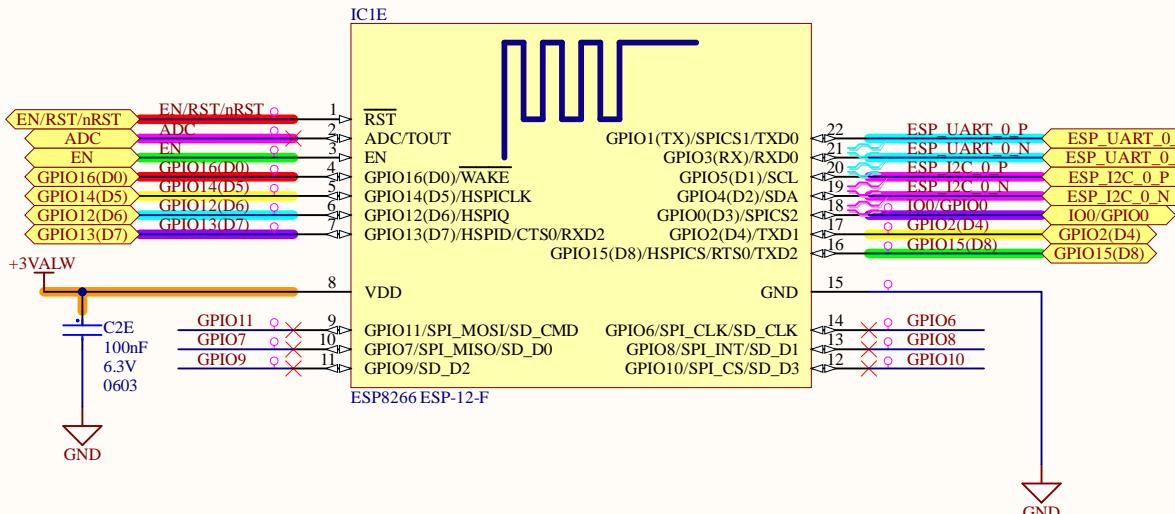
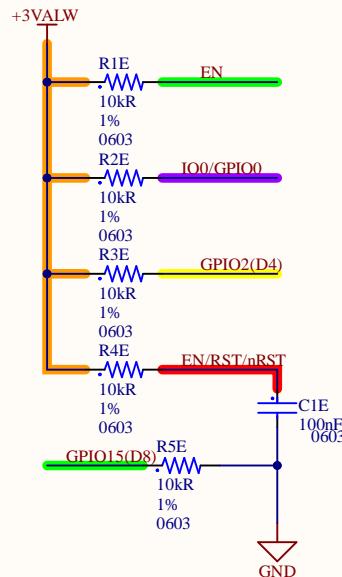
BEST PINS FOR INPUT (BEST TO WORST)

D1 = GPIO5
D2 = GPIO4
D5 = GPIO14
D6 = GPIO12
D7 = GPIO13
***HIGH ON BOOT**
D0 = GPIO16
SD2 = GPIO9
SD3 = GPIO10

BEST PINS FOR OUTPUT (BEST TO WORST)

D1 = GPIO5
D2 = GPIO4
D5 = GPIO14
D6 = GPIO12
D7 = GPIO13
***BOOT FAILURE IF PULLED HIGH**
D8 = GPIO15

BESP Pins For Smart LED(Pixel)
ESP8266_UART0 = GPIO1(TX)
ESP8266_UART1 = GPIO2(D4)
ESP8266_DMA = GPIO3(RX)
ESP8266_ASYNC_UART0 = GPIO1(TX)
ESP8266_ASYNC_UART1 = GPIO2(D4)
ESP8266_SPI_DATA = GPIO13(D7)
ESP8266_SPI_CLOCK = GPIO14(D5)



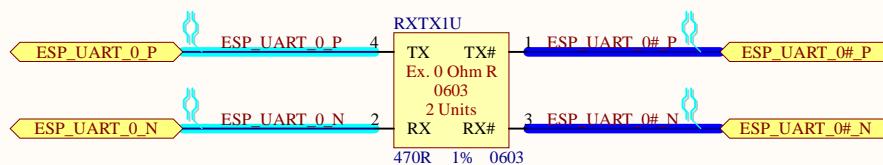
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Title: 3_ESP8266_Core.SchDoc	Author: Alcatraz	DHNLAB PVT LTD
Approved: Alcatraz		DHANBAD
PUBLIC		JHARKHAND
Edited: 04-12-2024		INDIA
Date: 06-12-2024 20:12:58	Variant: [No Variations]	ASIA
Git Hash: 464	SW Version: 24.10.1.45	
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\3_ESP8266_Core.SchDoc		



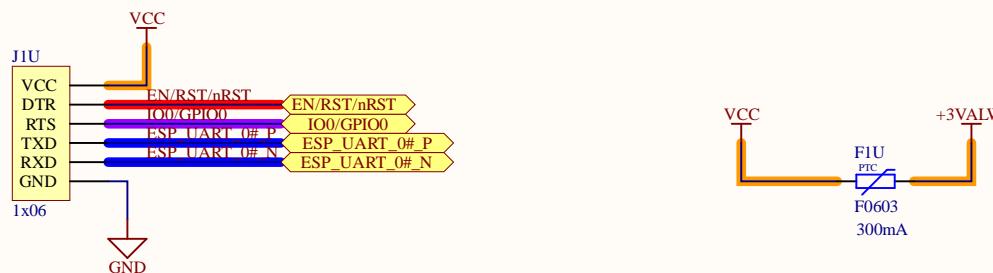
A

A



B

B



C

C

Title: 4_USB_TO_UART		Author: Alcatraz	DHNLAB PVT LTD DHANBAD JHARKHAND INDIA ASIA
Size: A4 Prj: ESP8266-Deskop_Power		Approved: Alcatraz	
Date: 06-12-2024 20:12:59		Edited: 02-12-2024	
Git Hash: 448		Variant: [No Variations]	
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Deskop_Power\4_USB_TO_UART.SchDoc			

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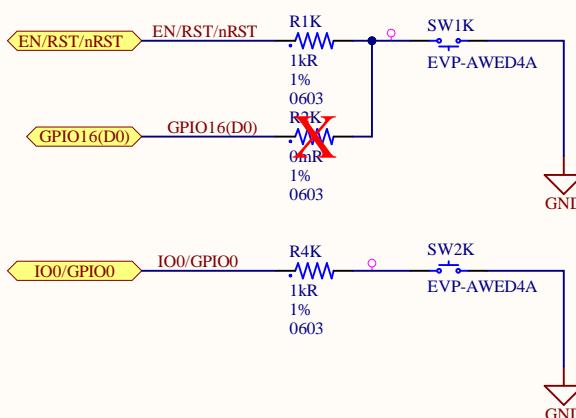
D

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Title: KEYS		Author: Alcatraz	DHNLAB PVT LTD DHANBAD JHARKHAND INDIA ASIA
Size: A4	Prj: ESP8266-Deskop_Power	Approved: Alcatraz	
Date: 06-12-2024 20:12:59	Sheet 5 of 10	Edited: 06-12-2024	
Git Hash: 480		Variant: [No Variations]	
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Devlopment\ESP8266-Deskop_Power\5_Keys.SchDoc		SW Version: 24.10.1.45	



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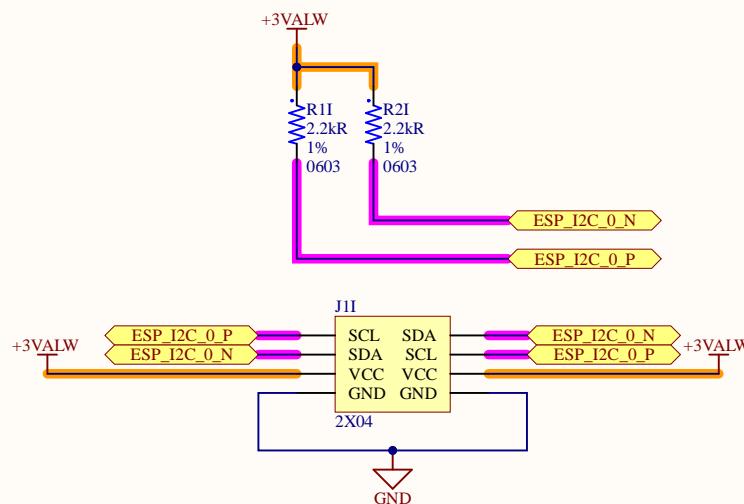
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Title: <i>I2C_Sensors</i>	Author: Alcatraz	DHNLAB PVT LTD
Approved: Alcatraz	Editor: PUBLIC	DHANBAD
Size: A4	Edited: 02-12-2024	JHARKHAND
Prj: ESP8266-Desktop_Power	Variant: [No Variations]	INDIA
Date: 06-12-2024 20:12:59	SW Version: 24.10.1.45	ASIA
Git Hash: 442		
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\6_I2C_Sensors.SchDoc		



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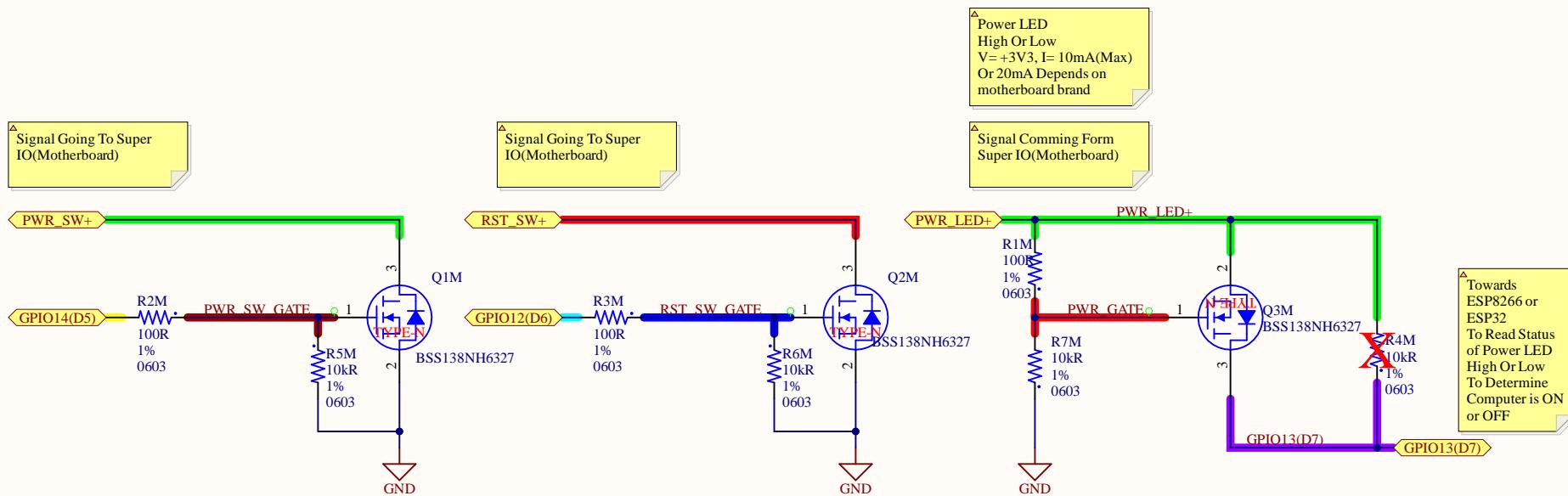
B

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Title: <i>Mosfets</i>	Author: Alcatraz	DHNLAB PVT LTD
Approved: Alcatraz	Editor: PUBLIC	DHANBAD
Size: A4	Date: 01-12-2024	JHARKHAND
Prj: ESP8266-Desktop_Power	Variant: [No Variations]	INDIA
	Git Hash: 438	ASIA
	File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\7_Mosfets.SchDoc	
	SW Version: 24.10.1.45	



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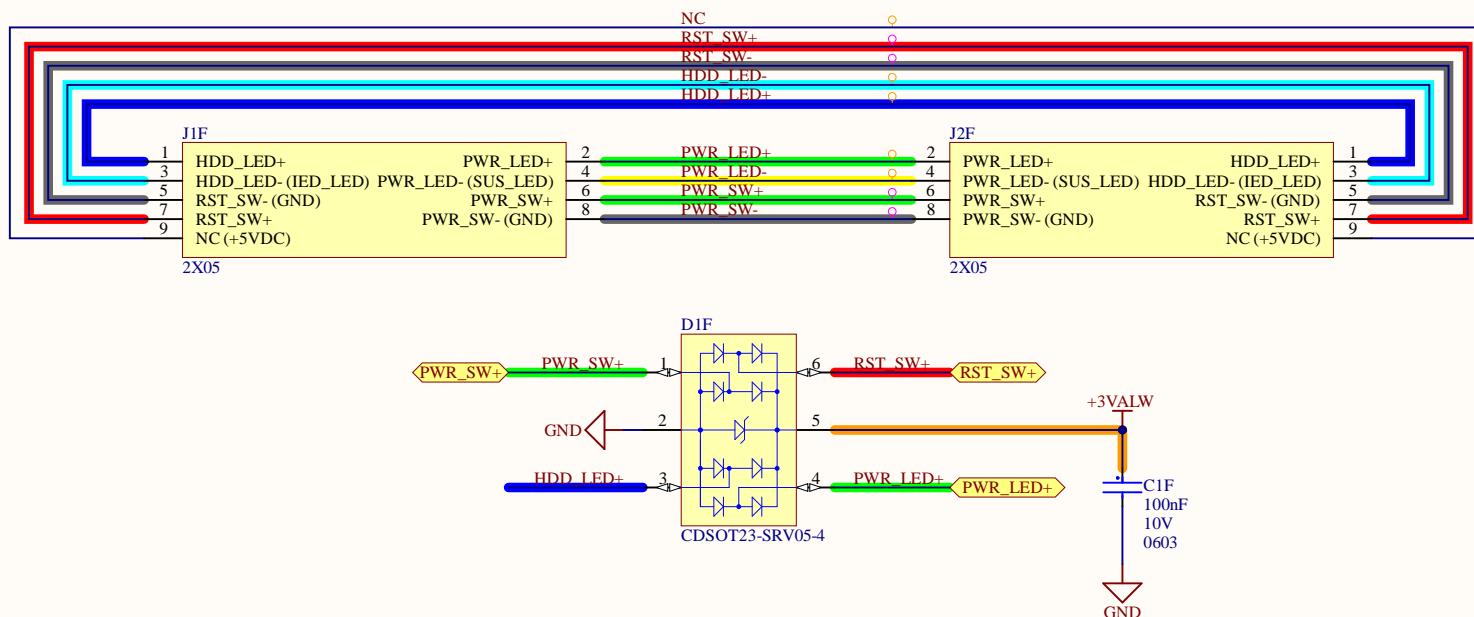
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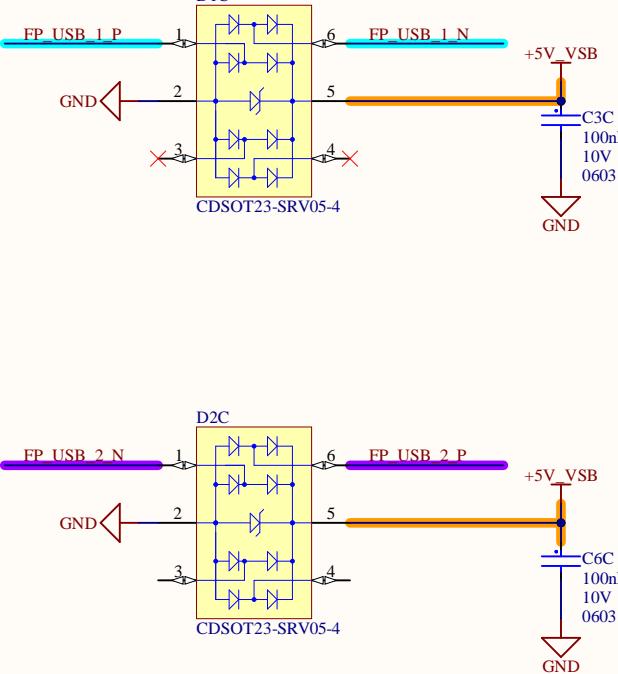
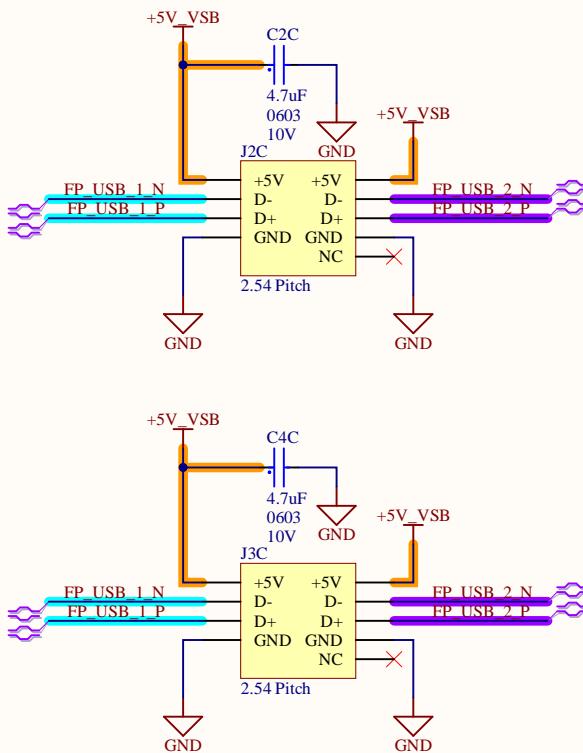
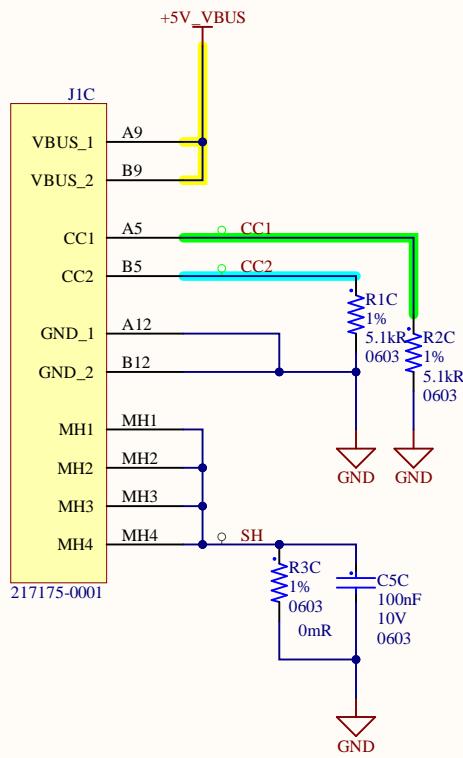


Title: <i>Front Pannel Con</i>	Author: Alcatraz	DHNLAB PVT LTD
Approved: Alcatraz	Edited: 24-11-2024	DHANBAD
Size: A4	Variant: [No Variations]	JHARKHAND
Prj: ESP8266-Desktop_Power	SW Version: 24.10.1.45	INDIA
Date: 06-12-2024 20:12:59	File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\8_Front_Pannel_Con.SchDoc	ASIA
Git Hash: 438		



A

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Title: Front Pannel USB Con		Author: Alcatraz
Size: A4	Prj: ESP8266-Desktop_Power	Approved: Alcatraz
Date: 06-12-2024 20:12:59	Sheet 9 of 10	Edited: 24-11-2024
Git Hash: 437		Variant: [No Variations]
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\9_Front_Pannel_USB Con.SchDoc		SW Version: 24.10.1.45

DHNLAB PVT LTD
DHANBAD
JHARKHAND
INDIA
ASIA



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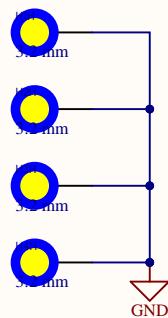
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Title: MountingHoles		Author: Alcatraz	DHNLAB PVT LTD DHANBAD JHARKHAND INDIA ASIA
Size: A4 Prj: ESP8266-Desktop_Power		Approved: Alcatraz	
Date: 06-12-2024 20:12:59		Edited: 23-11-2024	
Git Hash: 436		Variant: [No Variations]	
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\10_MountingHoles.SchDoc		SW Version: 24.10.1.45	



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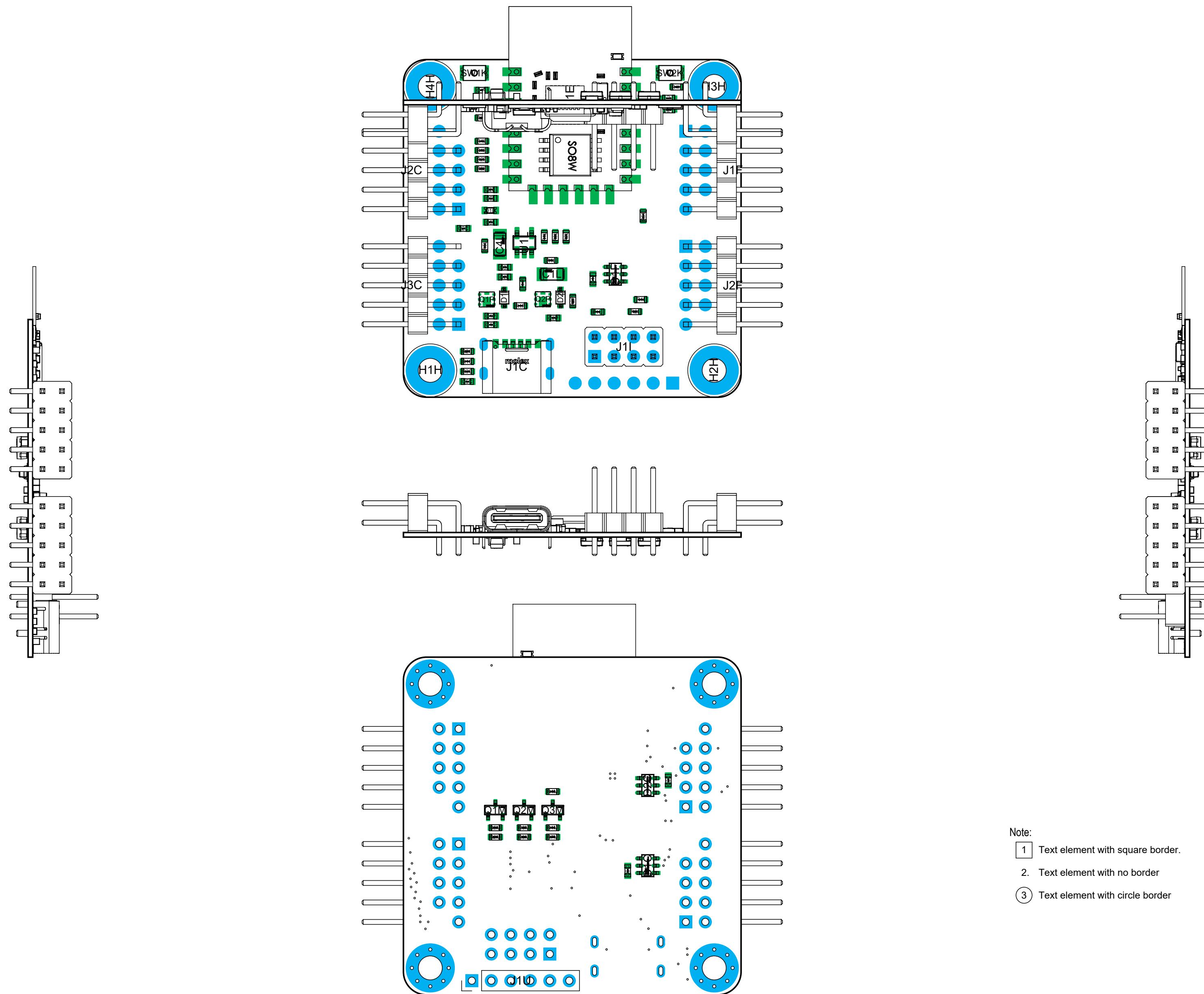
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WRITTEN PERMISSION OF IS
PROPRIETARY AND CONFIDENTIAL

		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES	NAME	DATE
		TOLERANCES: FRACTIONAL: ± ANGULAR: MACH: ± BEND: ± TWO PLACE DECIMAL: ± THREE PLACE DECIMAL: ±	DRAWN	06-12-2024
			CHECKED	
			ENG APPR.	
			MFG APPR.	
		INTERPRET GEOMETRIC TOLERANCING PER:	Q.A.	
			MATERIAL	COMMENTS:
	NEXT ASSY	USED ON	FINISH	
			APPLICATION	DO NOT SCALE DRAWING
				SCALE: 1:1 WEIGHT: SHEET 1 OF 1

PCB MANUFACTURING SPECIFICATIONS

"=ProjectTitle"

SPECIFICATIONS

NOTE #	NOTE
1	ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK
2	SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION
3	ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY THE TEXT "PLACE MARKINGS HERE"
4	COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS
5	ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-CONDUCTIVE, PERMANENT INK.
6	MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM_NOTES" BY THE TEXT "PLACE MARKINGS HERE".
7	MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRETION UNLESS OTHERWISE NOTED ONTO THE LAYER "PCBM_NOTES"
8	SUPPLIER SHALL CHECK PCBM_NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS
9	MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
	Surface Material	0.02mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
	Core	0.50mm	FR-4	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
	Surface Material	0.02mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 0.60mm

NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY
LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE

SPECIFICATIONS

LENGTH	44.00mm
WIDTH	44.00mm
LAYERS	2
MATERIAL	FR-4
MATERIAL MIN TG	130-140
TRACK WIDTH/CLEARANCE	10 mils / 10 mils
THICKNESS	0.6mm
COPPER THICKNESS	35um (1oz)
SOLDERMASK	YES, TOP AND BOTTOM
SOLDERMASK COLOR	GREEN
SILKSCREEN	YES, TOP AND BOTTOM
SILKSCREEN COLOR	WHITE
SURFACE FINISH	HASL LEAD FREE
GOLD FINGERS	NO
CHAMFERING	YES
IMPEDANCE CONTROL	YES
HALF-CUT/CASTELLATED HOLES	NO
BURIED/BLIND VIAS	NO
VIAS FILLED WITH RESIN	NO
CARBON MASK	NO
COUNTERSINKS/COUNTERBORES	NO
Z-AXIS MILLING	NO
PEELABLE SOLDERMASK	NO

Title: =ProjectTitle	Author:	CONFIDENTIAL
Size: A3	Approved:	My Company
Unit: mm	Edited: 06-12-2024	Address Line 1
Prj: =ProjectTitle	Variant: [No Variations]	Address Line 2
Date: 06-12-2024 08:13	FMSheet 1 of 3	Address Line 3
Git Hash:	SW version: 24.10.1.45	Address Line 4
File:C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB_MANUFACTURING_E		

[YOUR LOGO HERE]

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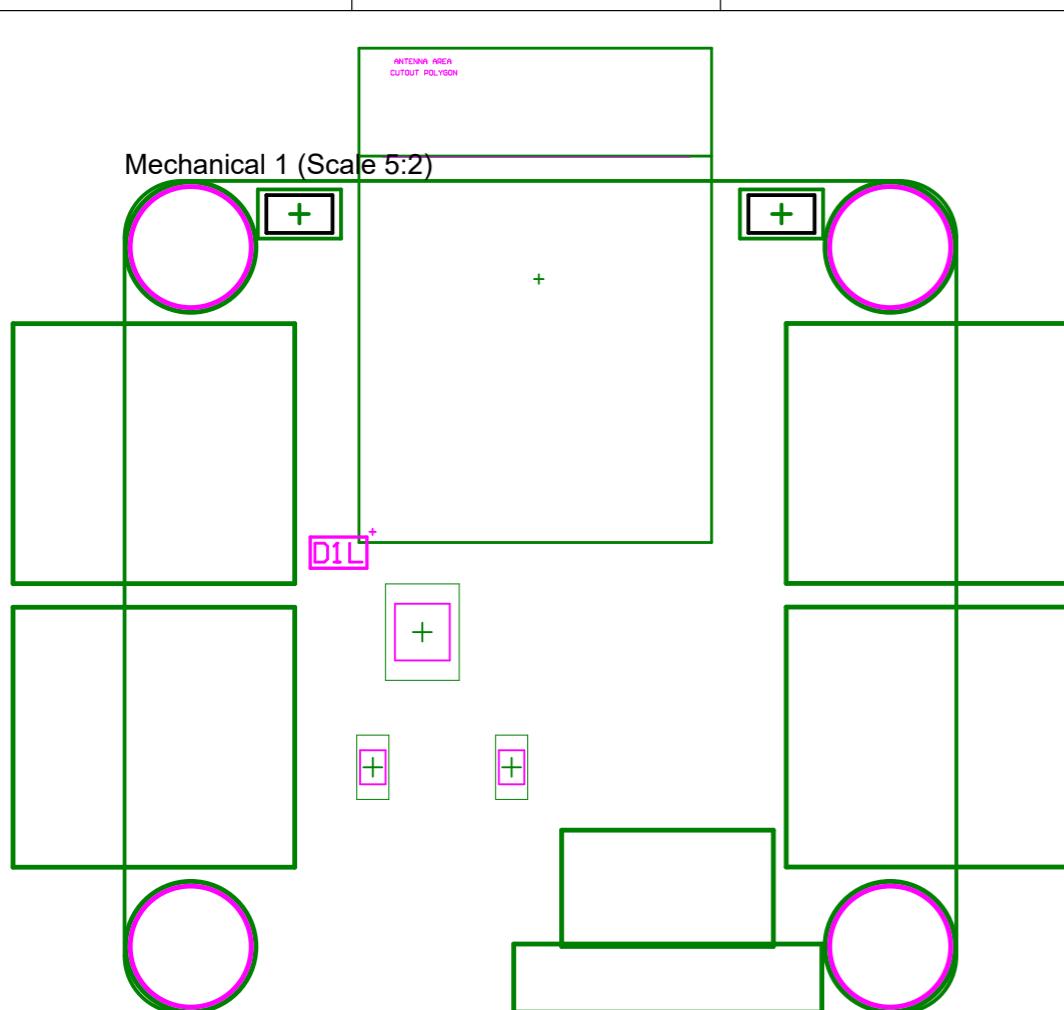
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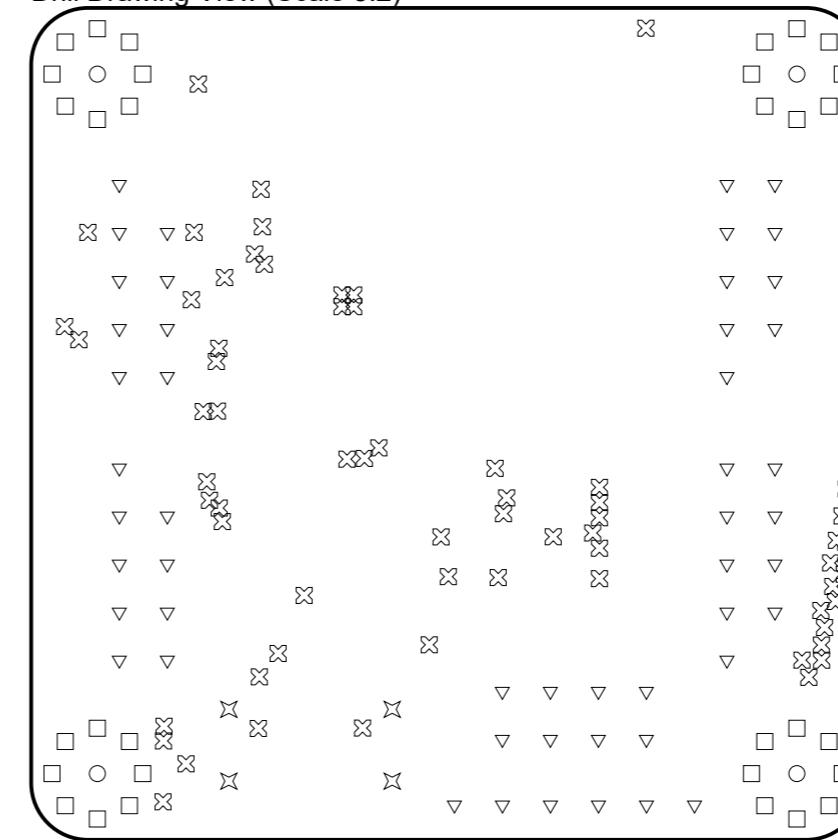
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Drill Drawing View (Scale 5:2)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
✗	66	0.30mm	Есть	
□	32	0.50mm	Есть	
▽	50	1.00mm	Есть	
☒	4	1.20mm	Есть	
○	4	3.20mm	Есть	
156 Total				

ALWAYS CAREFULLY READ
THE NOTES ON THIS LAYER!

Title: =ProjectTitle	Author:	CONFIDENTIAL
Size: A3	Approved:	
Unit: mm	Edited: 06-12-2024	My Company
Prj: =ProjectTitle	Variant: [No Variations]	Address Line 1
Date: 06-12-2024 08:13	FMSheet 2 of 3	Address Line 2
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File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Deskop_Power\PCB_MANUFACTURING_E		Address Line 4

[YOUR LOGO
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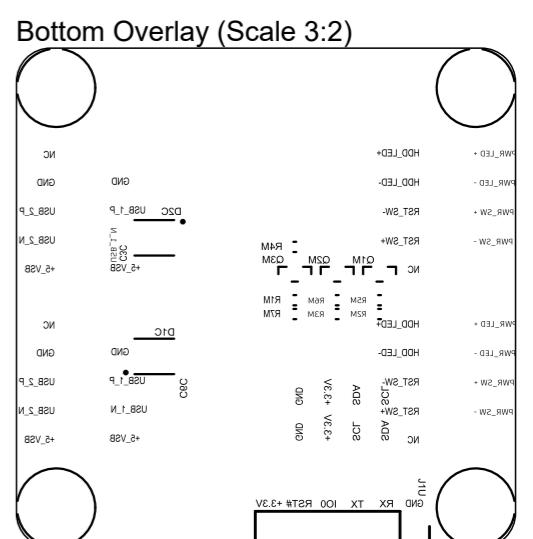
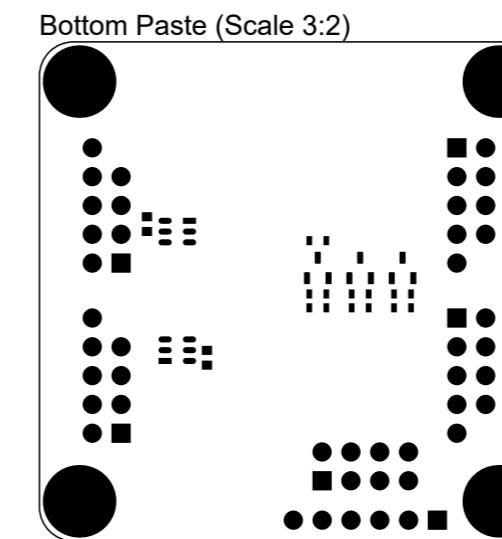
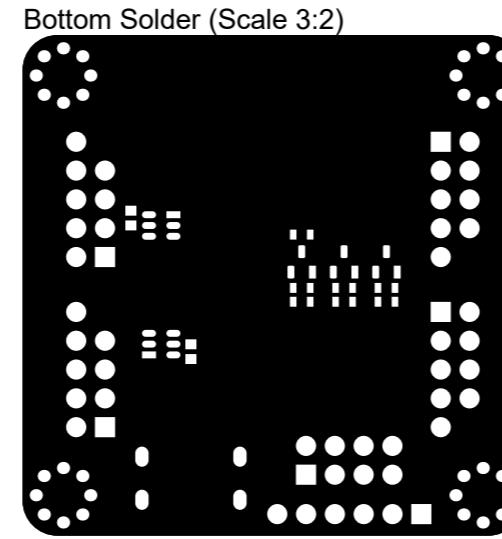
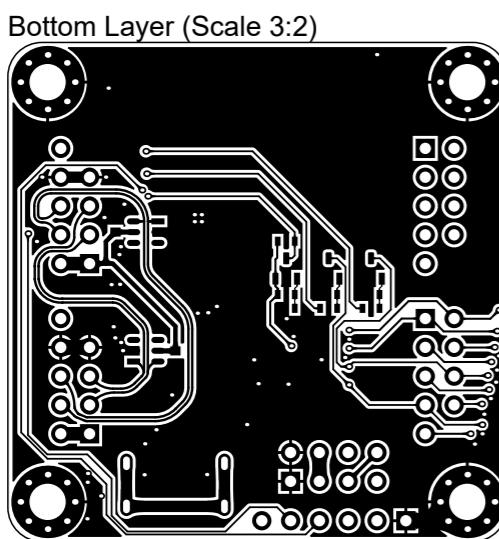
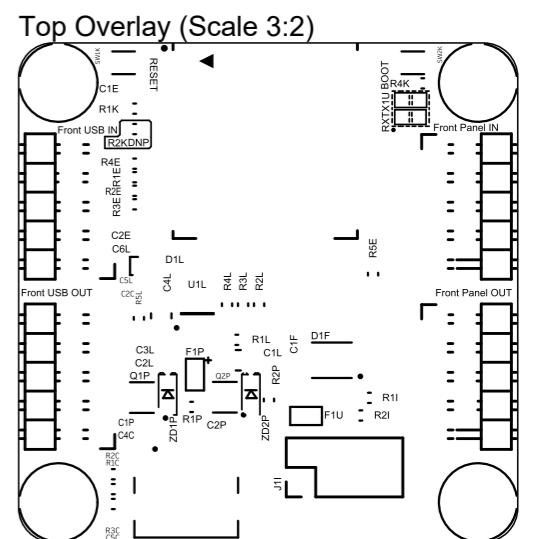
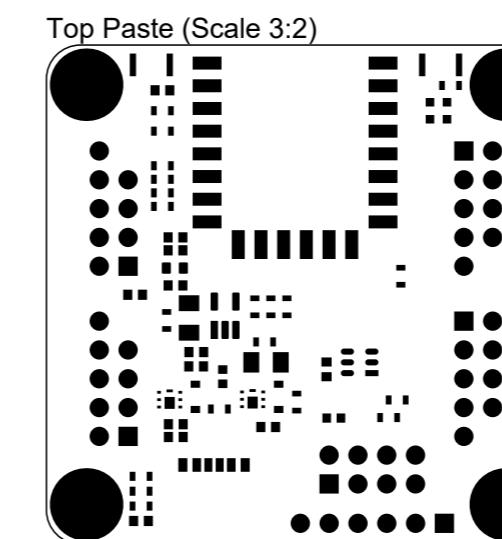
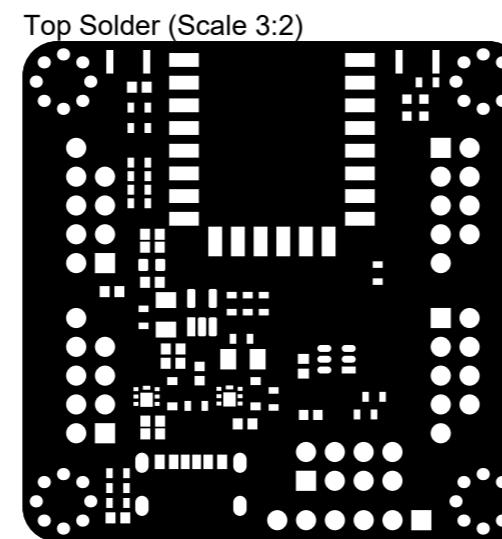
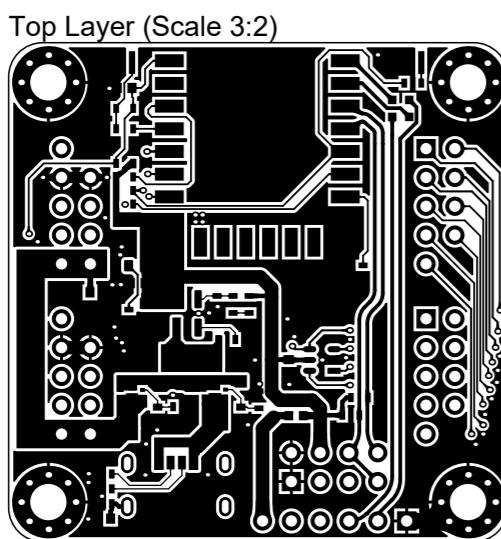
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Title: =ProjectTitle	Author:	CONFIDENTIAL
Size: A3	Approved:	
Unit: mm	Edited: 06-12-2024	
Prj: =ProjectTitle	Variant: [No Variations]	
Date: 06-12-2024 08:13	MSheet: 3 of 3	SW version: 24.10.1.45
Git Hash: 486 [No modification]		
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB MANUFACTURING_E		

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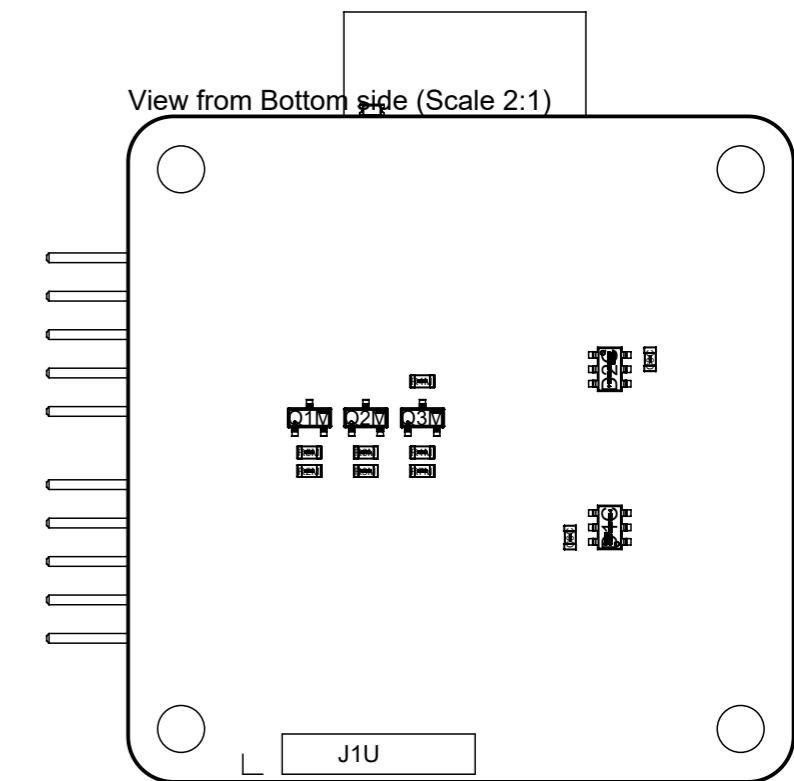
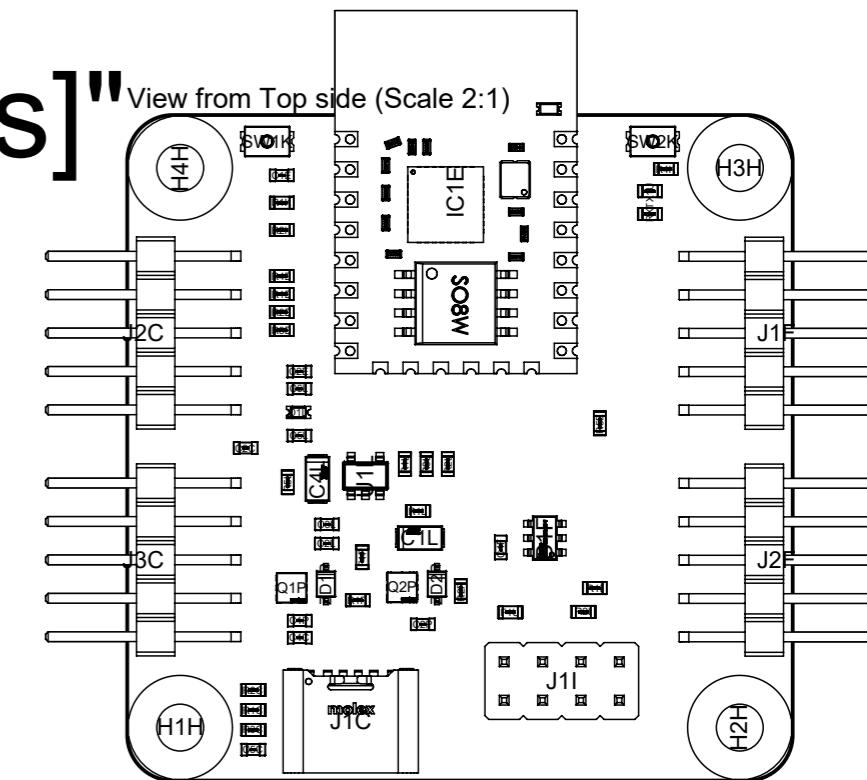
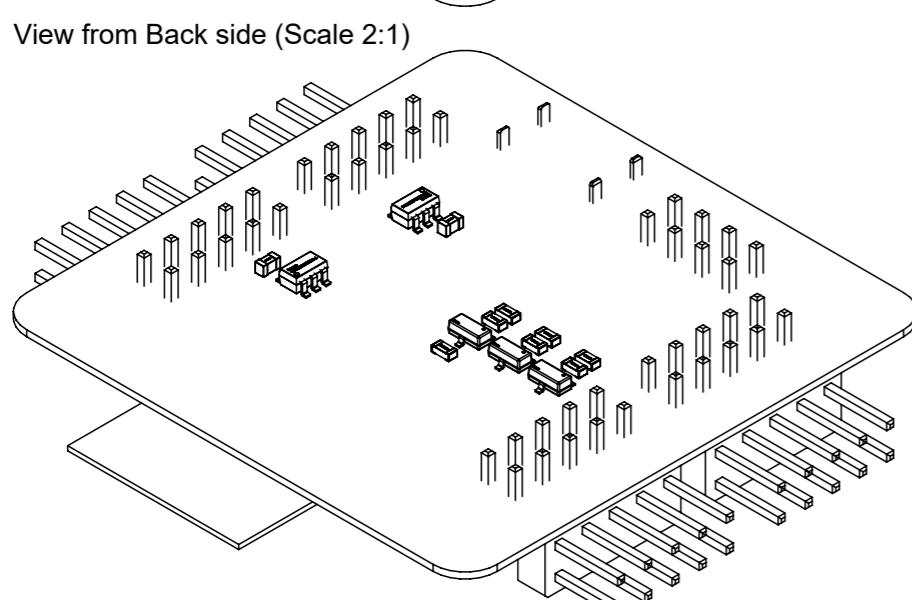
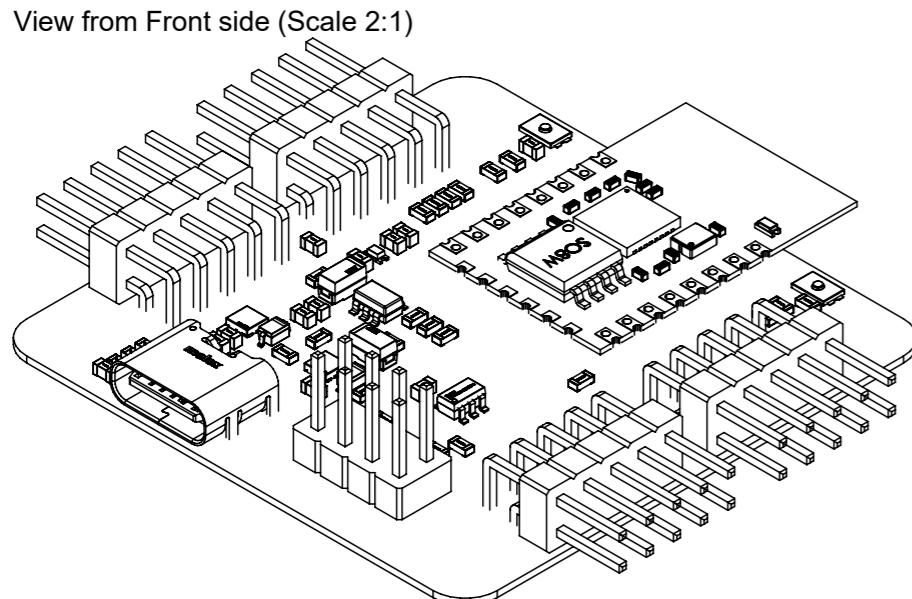
PCB ASSEMBLY SPECIFICATIONS

"=ProjectTitle"

Variant: "[No Variations]"

SPECIFICATIONS

NOTE #	NOTE
1	ALL SPECIFICATIONS REFERENCED SHALL BE OF THE LATEST REVISION UNLESS OTHERWISE NOTED
2	SUPPLIER SHALL NOT MODIFY THE DESIGN WITHOUT WRITTEN PERMISSION
3	REFER TO EXCEL BOM FOR UP-TO-DATE INFORMATION
4	THE BOM IN THIS DOCUMENT IS PURELY AN AID TO ASSEMBLY OPERATIONS AND MAY NOT HAVE THE MOST UP-TO-DATE DATA OR ALL APPROVED COMPONENT ALTERNATIVE.



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Size: A3	Approved:	My Company
Prj: =ProjectTitle	Edited: 06-12-2024	Address Line 1
Unit: mm	Variant: [No Variations]	Address Line 2
Date: 06-12-2024 08:13	FMSheet 1 of 9	Address Line 3
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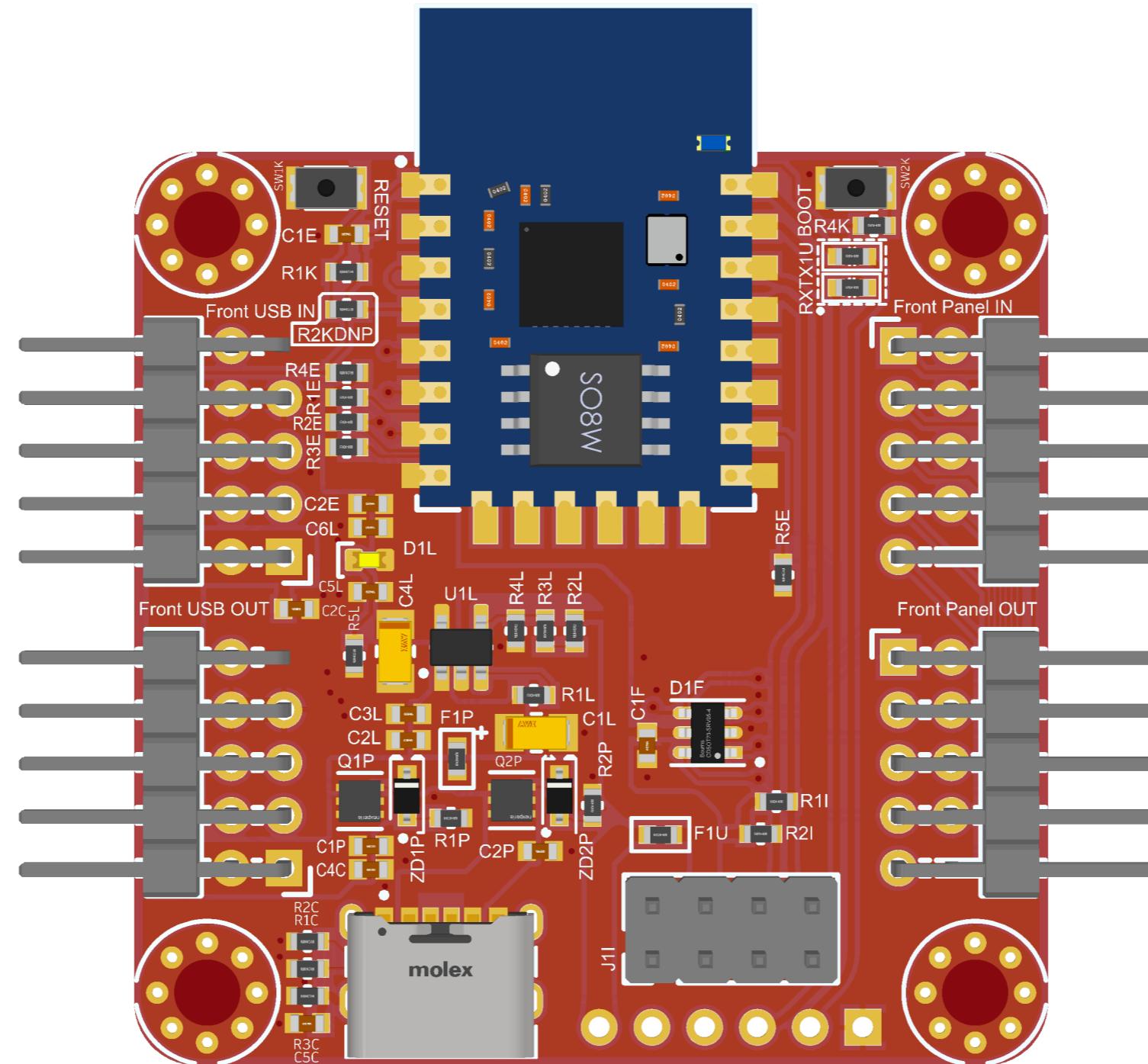
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Realistic View TOP



Title: =ProjectTitle	Author:	CONFIDENTIAL
Size: A3	Approved:	
Unit: mm	Edited: 06-12-2024	
Prj: =ProjectTitle	Variant: [No Variations]	
Date: 06-12-2024 08:13	FMSheet: 2 of 9	SW version: 24.10.1.45
Git Hash: 486 [No modification]		
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB_ASSEMBLY_ESP8266		

[YOUR LOGO HERE]

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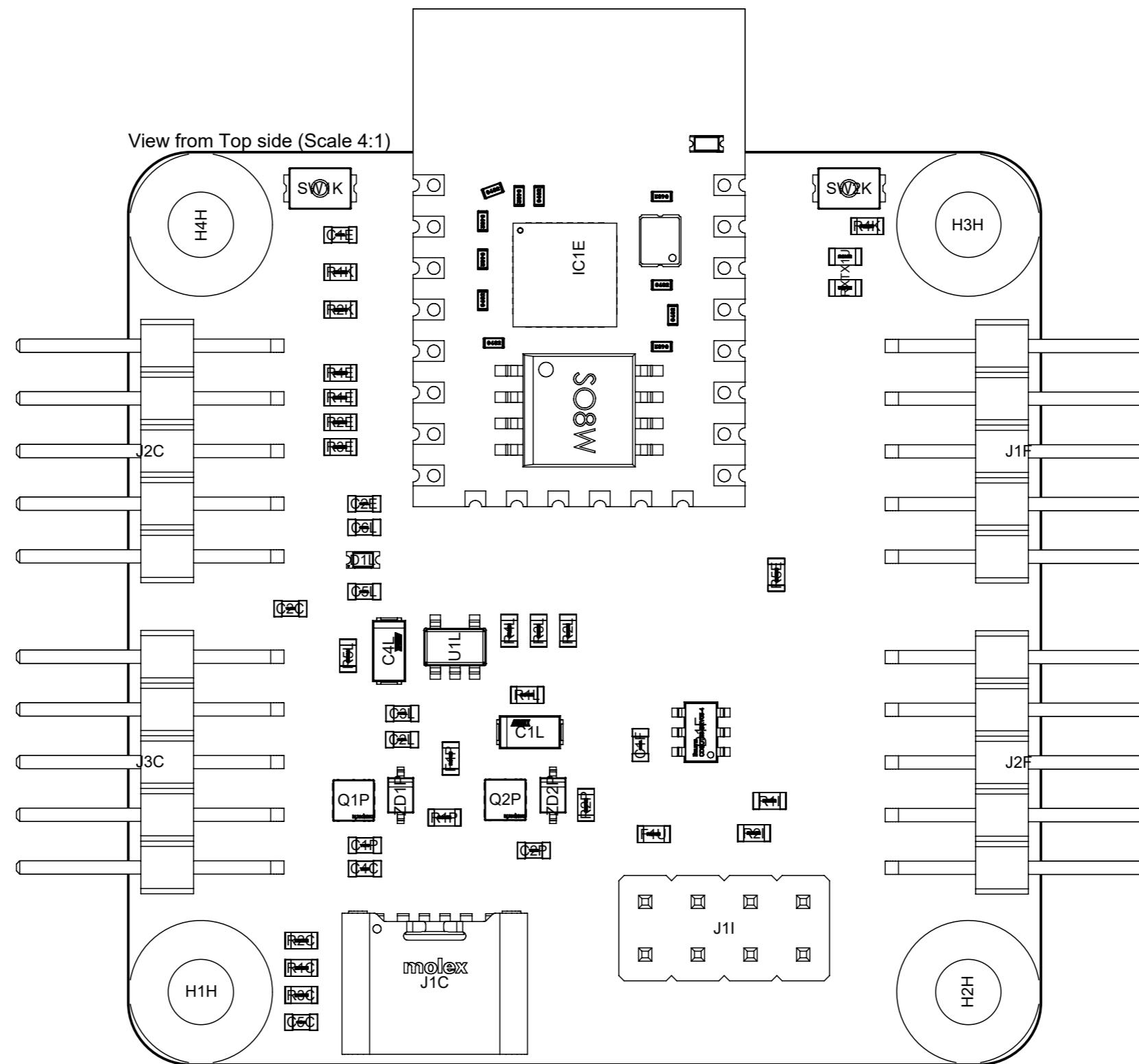
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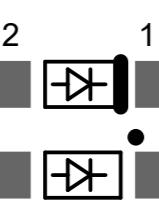
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DIODE ORIENTATION

Name	ANODE
Short name	A
Pin number	2
Silkscreen	thin line
assembly view	no dot ()



Name	CATHODE
Short name	K
Pin number	1
Silkscreen	thick line / dot
assembly view	dot (*)

Title: =ProjectTitle

Size: A3 Prj: =ProjectTitle

Unit: mm

Date: 06-12-2024 08:13 FMSheet 3 of 9

Git Hash: 486 [No modification]

File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB_ASSEMBLY_ESP8266

Author:

Approved:

Edited: 06-12-2024

Variant: [No Variations]

SW version: 24.10.1.45

CONFIDENTIAL

My Company

Address Line 1

Address Line 2

Address Line 3

Address Line 4

[YOUR LOGO HERE]

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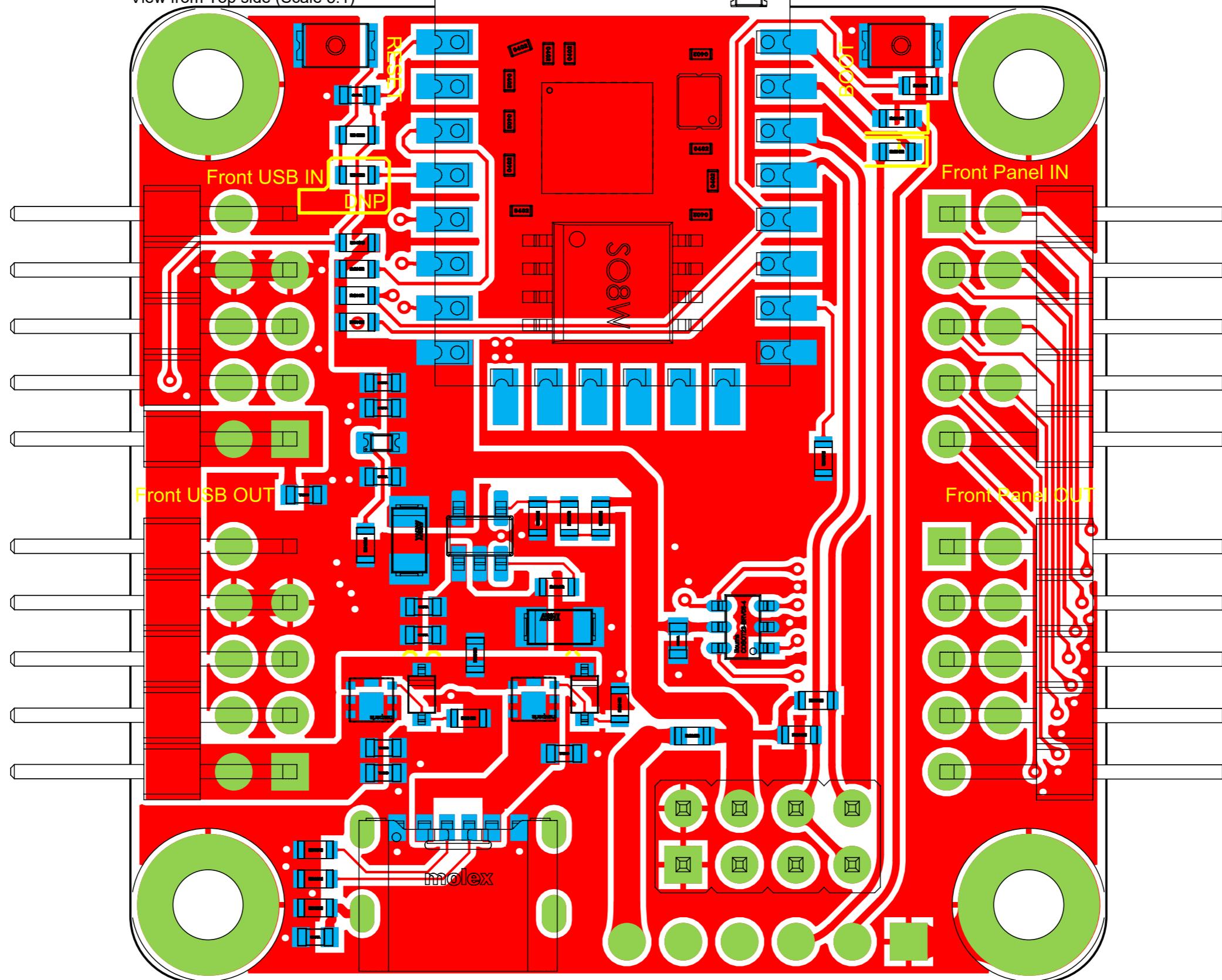
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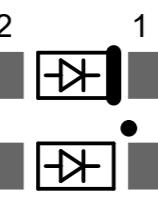
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View from Top side (Scale 5:1)



DIODE ORIENTATION

Name	ANODE
Short name	A
Pin number	2
Silkscreen	thin line
assembly view	no dot ()



Name	CATHODE
Short name	K
Pin number	1
Silkscreen	thick line / dot
assembly view	dot (•)

Title: =ProjectTitle

Author:

CONFIDENTIAL

Size: A3 Prj: =ProjectTitle

Approved:

My Company

Unit: mm

Edited: 06-12-2024

Address Line 1

Date: 06-12-2024 08:13 PM Sheet 4 of 9

Variant: [No Variations]

Address Line 2

Git Hash: 486 [No modification]

SW version: 24.10.1.45

Address Line 3

File:C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB ASSEMBLY ESP8266

Address Line 4

YOUR LOGO
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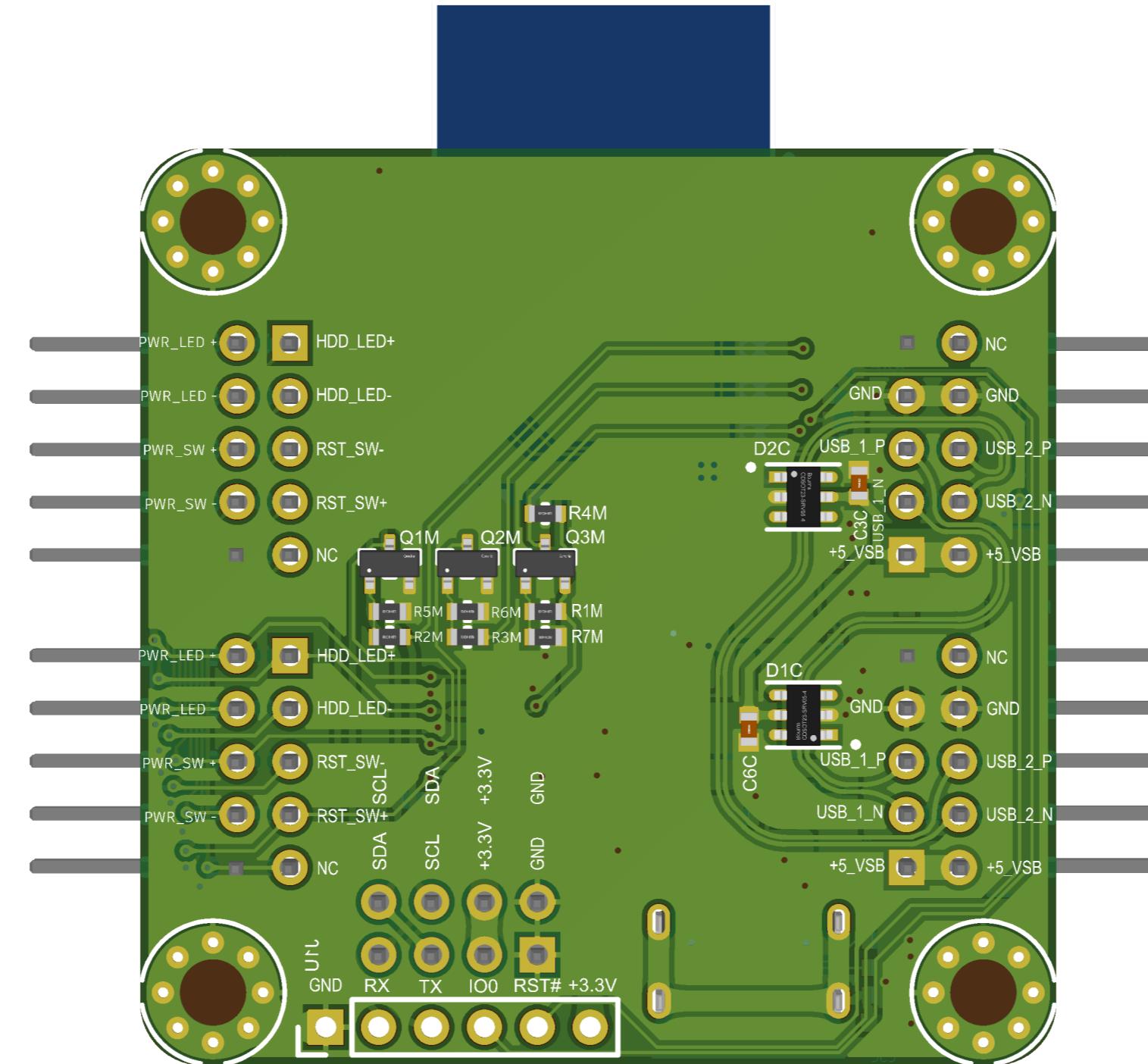
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Realistic View BOTTOM



Title: =ProjectTitle	Author:	CONFIDENTIAL
Size: A3	Approved:	My Company
Unit: mm	Edited: 06-12-2024	Address Line 1
Prj: =ProjectTitle	Variant: [No Variations]	Address Line 2
Date: 06-12-2024 08:13	FMSheet: 5 of 9	Address Line 3
Git Hash: 486 [No modification]	SW version: 24.10.1.45	Address Line 4
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB_ASSEMBLY_ESP8266		

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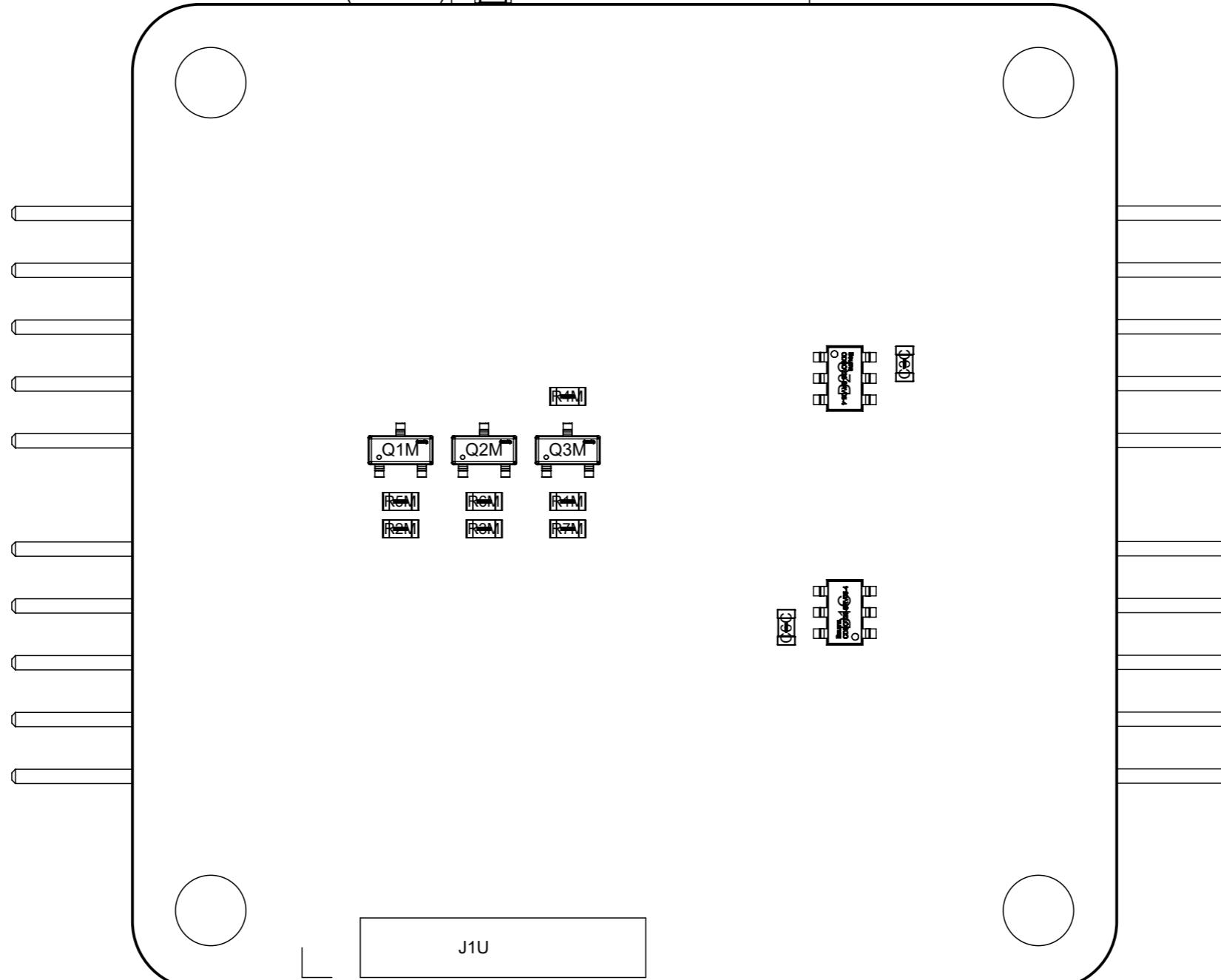
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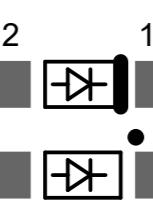
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View from Bottom side (Scale 4:1)



DIODE ORIENTATION

Name	ANODE
Short name	A
Pin number	2
Silkscreen	thin line
assembly view	no dot ()



Name	CATHODE
Short name	K
Pin number	1
Silkscreen	thick line / dot
assembly view	dot (•)

Title: =ProjectTitle

Author:

CONFIDENTIAL

Size: A3 Prj: =ProjectTitle

Approved: Edited: 06-12-2024

My Company

Unit: mm

Variant: [No Variations]

Address Line 1

Date: 06-12-2024 08:13 PM Sheet 6 of 9

SW version: 24.10.1.45

Address Line 2

Git Hash: 486 [No modification]

Address Line 3

Address Line 4

File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB_ASSEMBLY_ESP8266

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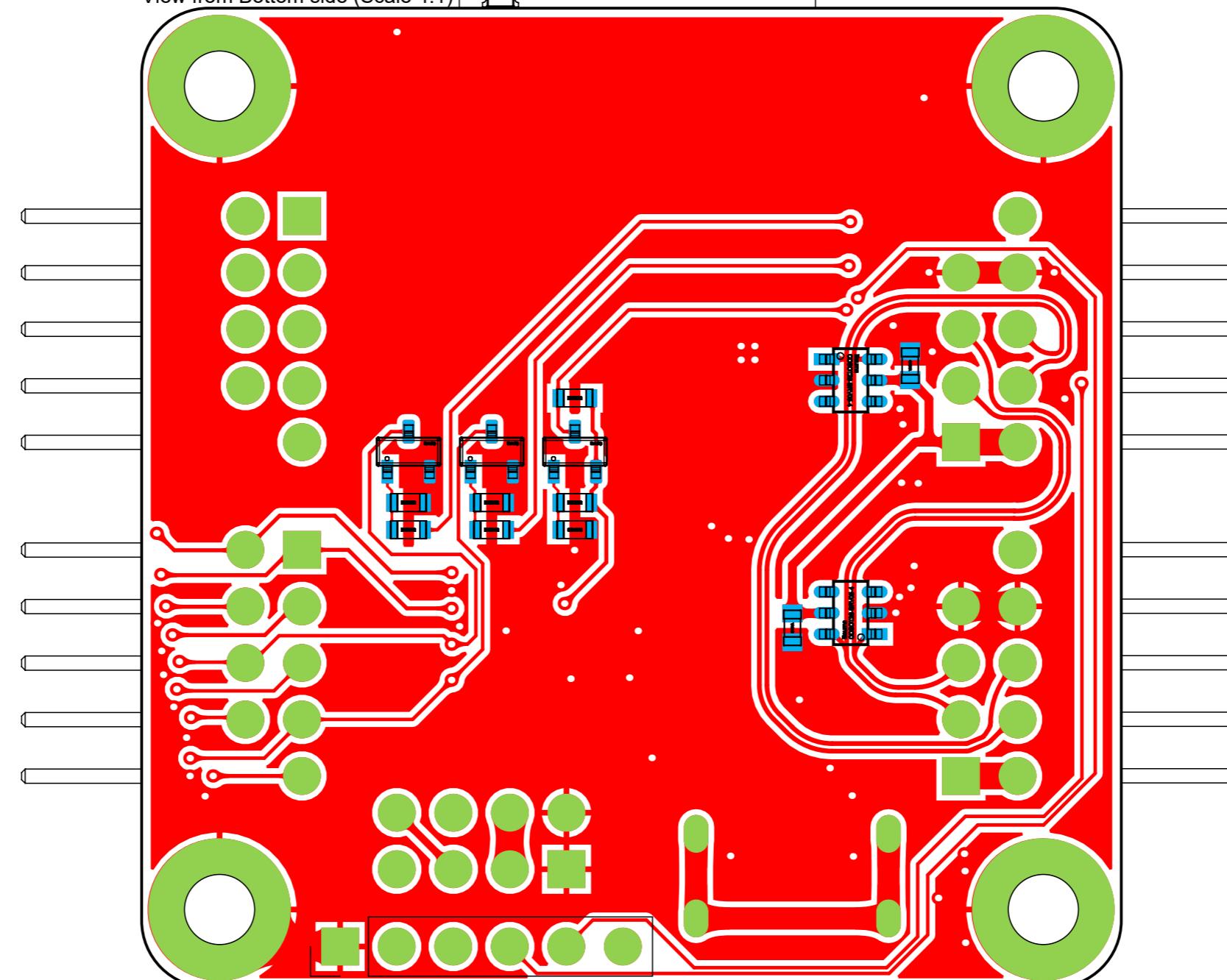
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View from Bottom side (Scale 4:1)



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DIODE ORIENTATION

Name	ANODE
Short name	A
Pin number	2
Silkscreen	thin line
assembly view	no dot ()



Name	CATHODE
Short name	K
Pin number	1
Silkscreen	thick line / dot
assembly view	dot (•)

Title: =ProjectTitle

Author:

CONFIDENTIAL

Size: A3 Prj: =ProjectTitle

Approved: Edited: 06-12-2024

My Company

Unit: mm Date: 06-12-2024 08:13 FMSheet 7 of 9

Variant: [No Variations] SW version: 24.10.1.45

Address Line 1

Git Hash: 486 [No modification]

Address Line 2

Address Line 3

File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB ASSEMBLY ESP8266

Address Line 4

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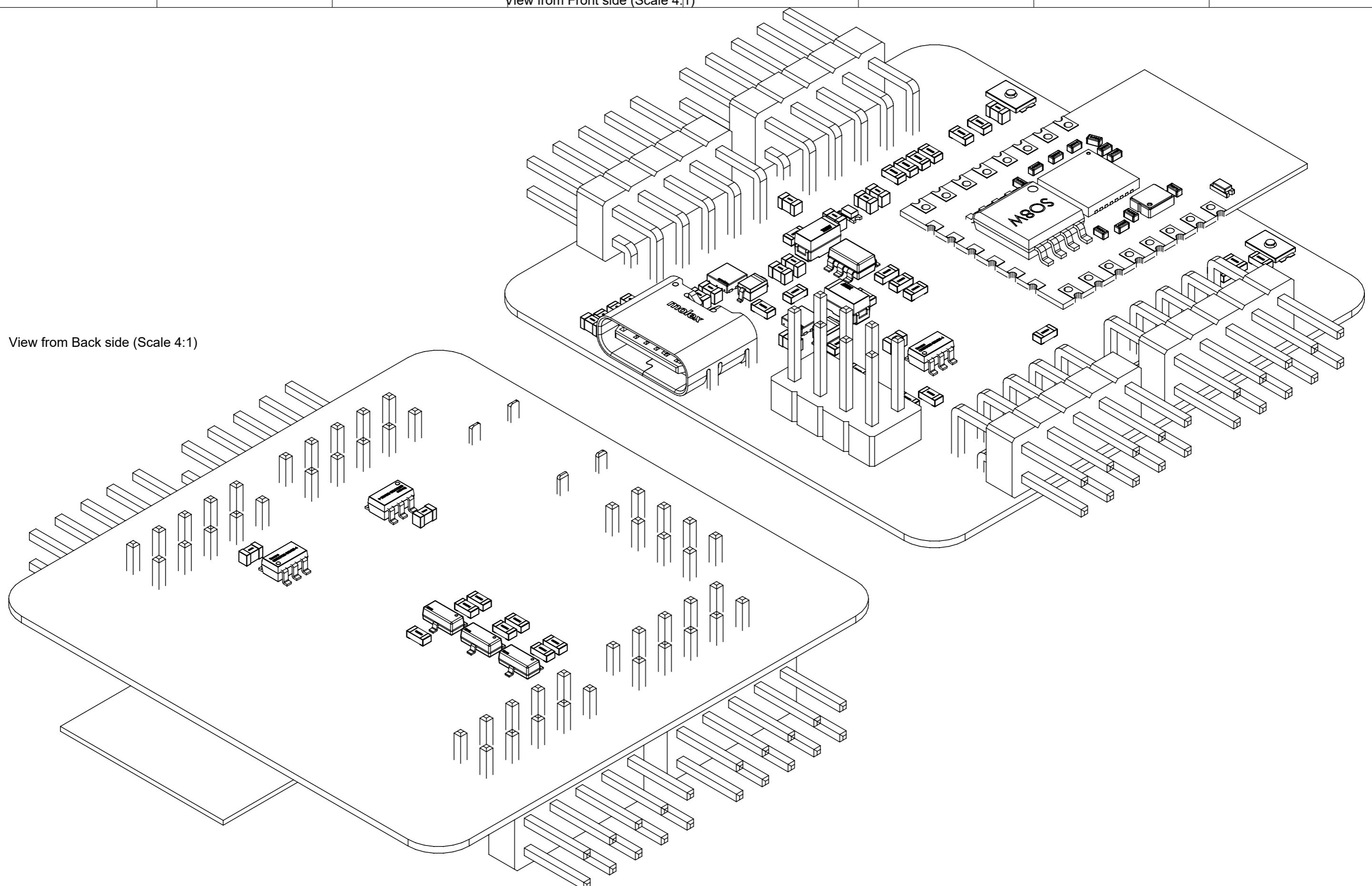
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View from Front side (Scale 4:1)

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Size: A3	Approved:	My Company
Unit: mm	Edited: 06-12-2024	Address Line 1
Prj: =ProjectTitle	Variant: [No Variations]	Address Line 2
Date: 06-12-2024 08:13	MSheet: 8 of 9	Address Line 3
Git Hash: 486 [No modification]	SW version: 24.10.1.45	Address Line 4
File: C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Desktop_Power\PCB ASSEMBLY_ESP8266		

[YOUR LOGO HERE]

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Bill Of Materials

Line #	Description	Designator	Quantity	Manufacturer Part Number 1	Part Number	Layer
	Cap Cer 0.1UF 6.3V X7R 0603	C1E, C2E	2	KGM15AR70J104KM		
	Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric]	C1F, C1P, C2P, C3C, C3L, C5C, C6C	7	C0603C104K8RAC786 7		
	Surface Mount Tantalum Capacitor, 47 uF, 10 V, ± 20%, -55 °C, 125 °C, 1206 [3216-12 Metric]	C1L	1			
	Multilayer Ceramic Capacitor, 4.7 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric]	C2C, C4C	2	CL10A475KP8NNNC		
	Multilayer Ceramic Capacitor, 22 uF, 10 V, ± 20%, X5R, 0603 [1608 Metric]	C2L	1	GRM188R61A226ME1 5D		
	47uF Solid MnO2 Tantalum Electrolytic Capacitor; 6.3 V dc +/-20%; T491 Series	C4L	1	T491A476M006AT		
	Multilayer Ceramic Capacitor, 22 uF, 6.3 V, ± 20%, X5R, 0603 [1608 Metric]	C5L, C6L	2	GRM188R60J226MEA 0D		
	TVS DIODE 5V 15V SOT23-6	D1C, D1F, D2C	3			
	LED 0603 YELLOW SMD	D1L	1			
	Fuse PPTC SMD 0603	F1P	1			
	Fuse PPTC SMD 0603	F1U	1			
		H1H, H2H, H3H, H4H	4			
	ESP8266 ESP-12-F	IC1E	1			
	Connector USB Type C Female 6Positions 0.5mm Right Angle SMT Embossed T/R - Tape and Reel	J1C	1			
		J1F, J2F	2			
		J1I	1			
		J1U	1			
		J2C, J3C	2			
	Single N-Channel 60 V 3.5 Ohm 1 nC SiPMOS® Small Signal Mosfet - SOT-23 PMPB14XPZ	Q1M, Q2M, Q3M	3	BSS138N		
	SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	Q1P, Q2P	2	PMPB14XPZ		
	SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1C, R2C	2	CRCW06035K10FKEA		
	SMD Chip Resistor, 2.2 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1E, R1L, R2E, R3E, R4E, R4M, R5E, R5M, R6M, R7M	10	RC0603FR-0710KL		
	SMD Chip Resistor, 1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1I, R2I	2	RC0603FR-072K2L		
	SMD Chip Resistor, 100 Ohm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1K, R4K	2	RC0603FR-101KL		
	SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1M, R2M, R3M	3	AC0603FR-07100RL		
	Zero Ohm Resistor, Jumper, 0603 [1608 Metric], Thick Film, 100 mW, 1 A, Surface Mount	R2K, R3C	2	RC0603JR-070RL		
	Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 100 PPM	R2L	1	MCR03EZPFX1691		
	Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100ppm/C Pad SMD Automotive T/R	R3L	1	ERJ-3EKF3302V		
	SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R4L	1	CR0603-FX-2002ELF		
	Res Thick Film 0603 2.49K Ohm 1% 1/10W ±100ppm/°C Molded SMD SMD Paper T/R	R5L	1	MCR03EZPFX2491		
	UART RX/TX Pokayoke	RXTX1U	1			
	3.0MM X 2.0MM / 3.3N / 0.15MM ST	SW1K, SW2K	2	EVP-AWED4A	EVP-AWED4A	
	LDO U-Reg Adj 0, 3A SOT23-5	U1L	1			
	MM3Z12VST1G Zener Diode, 12V 2% 200 mW SMT 2-Pin SOD-323 ON Semiconductor MM3Z12VST1G	ZD1P, ZD2P	2			

Please consider LCSC (立创商城) as our first supplier

BOM FOR REFERENCE ONLY

ALWAYS REFER TO THE LATEST EXCEL BOM PROVIDED

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Size: A3	Approved:	My Company Address Line 1 Address Line 2 Address Line 3 Address Line 4
Unit: mm	Edited: 06-12-2024	
Prj: =ProjectTitle	Variant: [No Variations]	
Date: 06-12-2024 08:13	MSheet 9 of 9	
Git Hash: 486 [No modification]		
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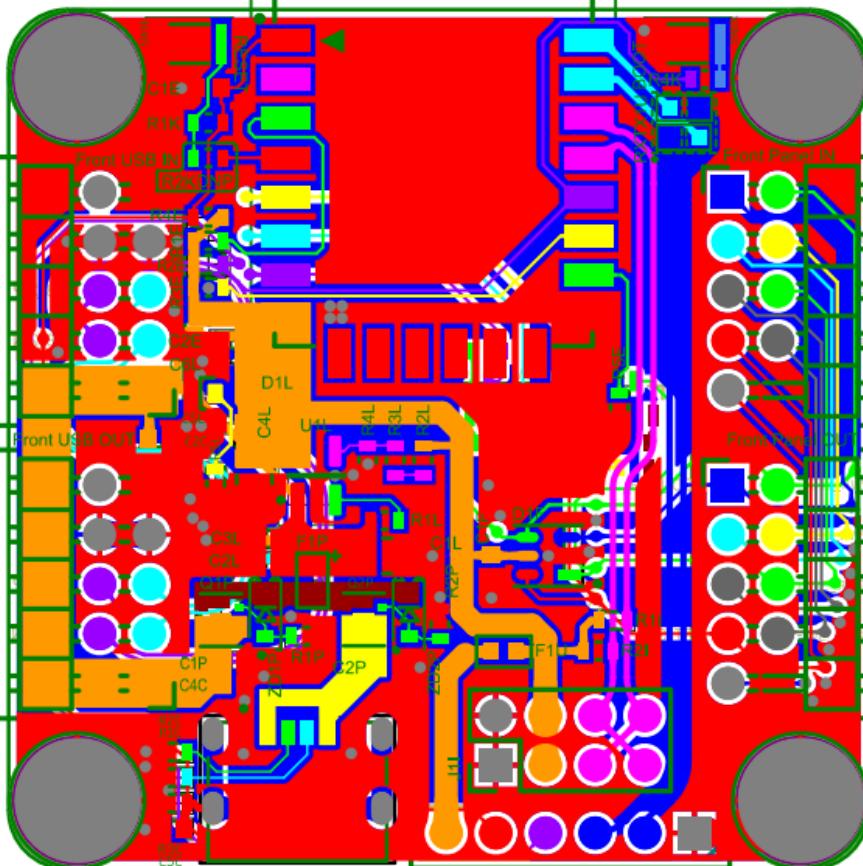
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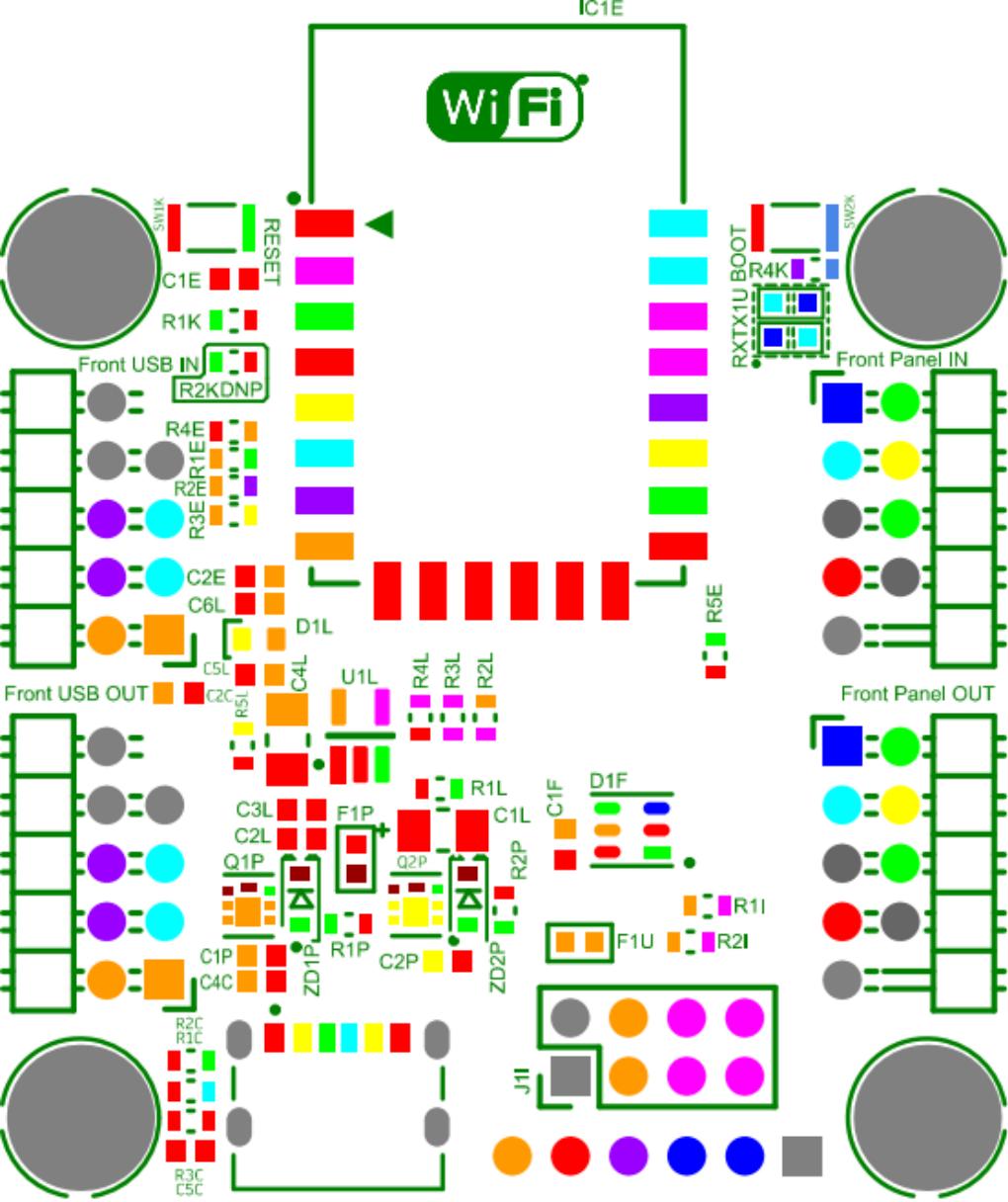
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IC1E

ANTENNA AREA
CUTOUT POLYGON





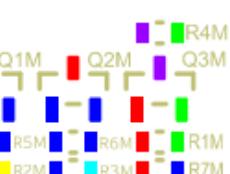


PWR_LED + HDD_LED+

PWR_LED - HDD_LED-

PWR_SW + RST_SW-

PWR_SW - RST_SW+

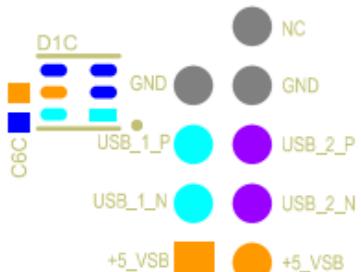
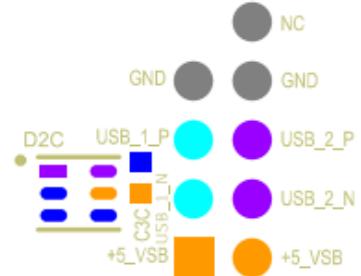


PWR_LED + HDD_LED+

PWR_LED - HDD_LED-

PWR_SW + RST_SW-

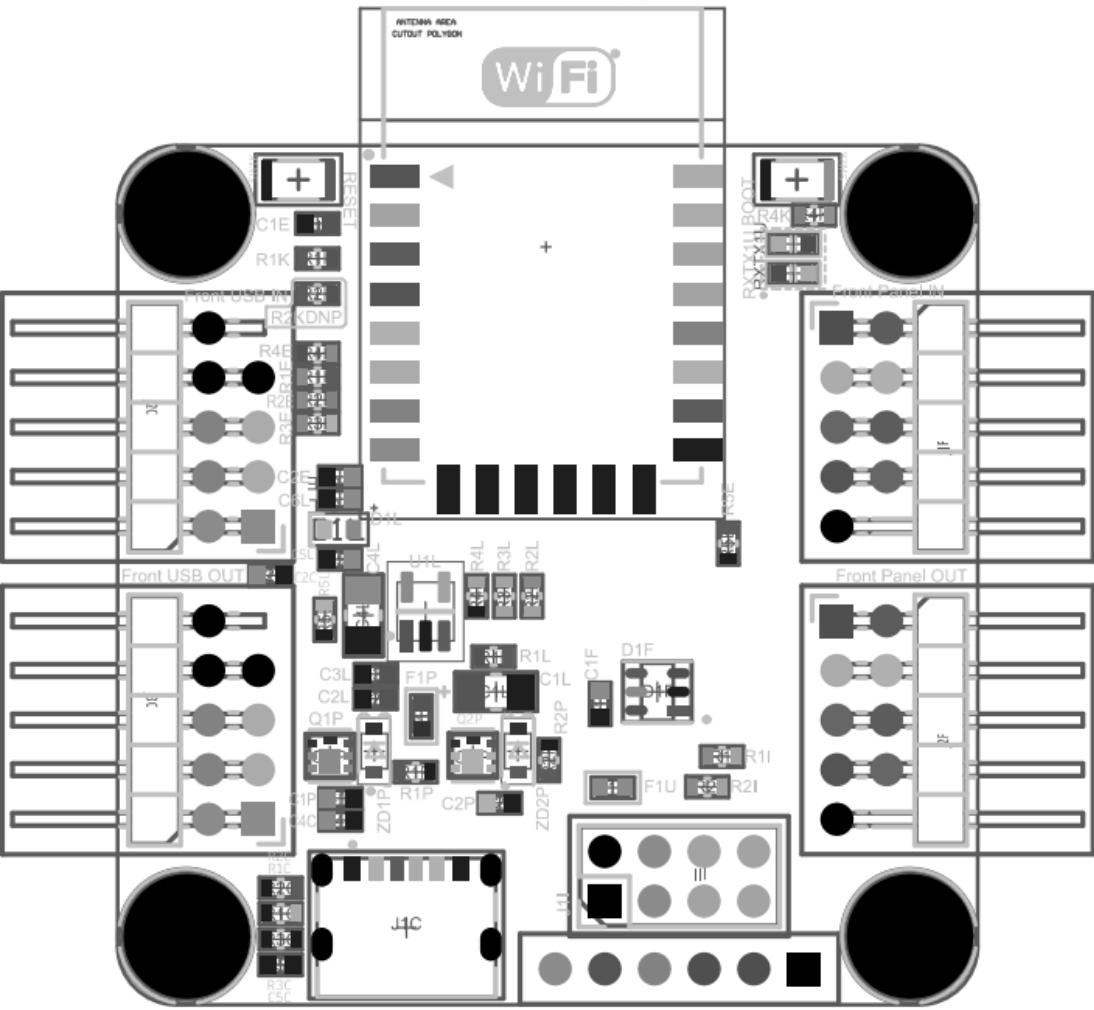
PWR_SW - RST_SW+

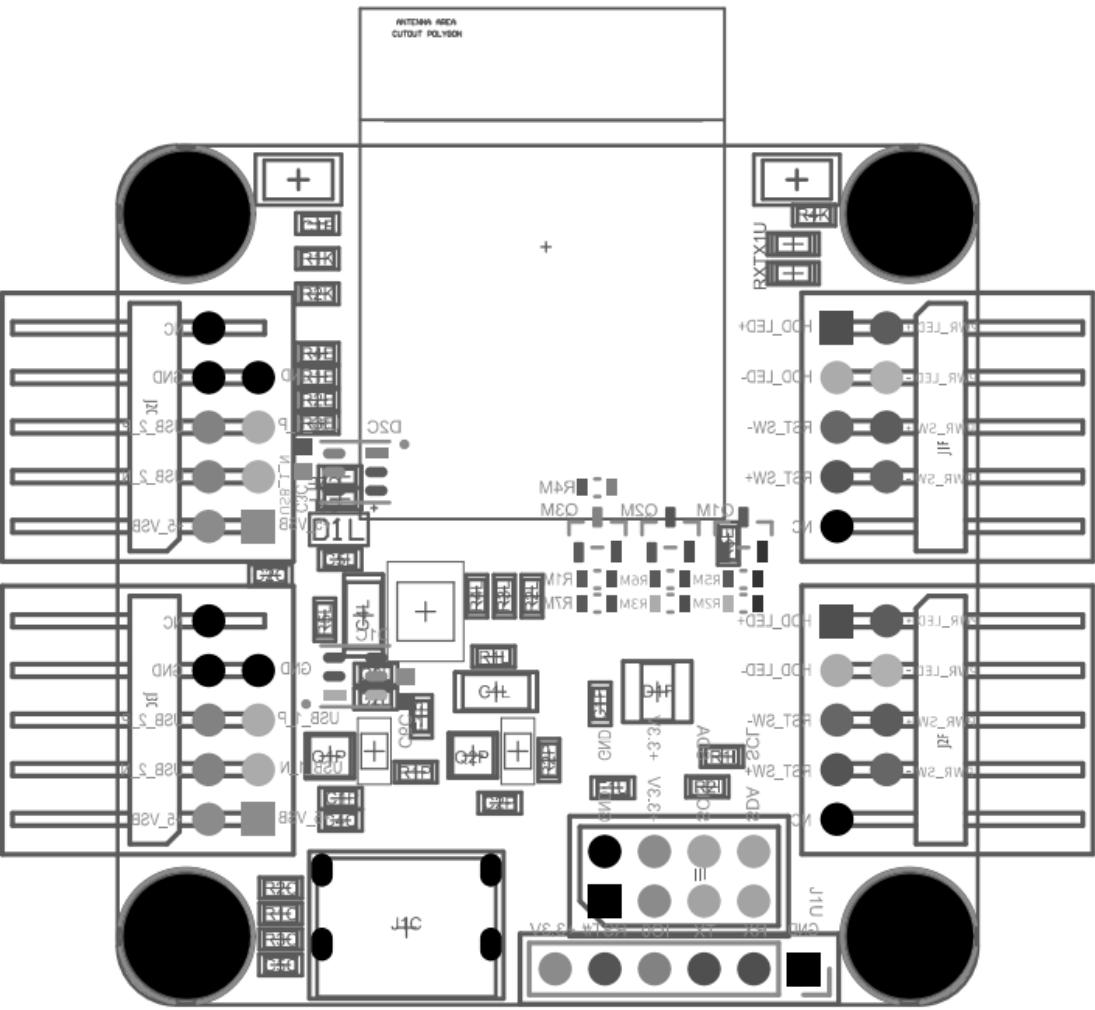


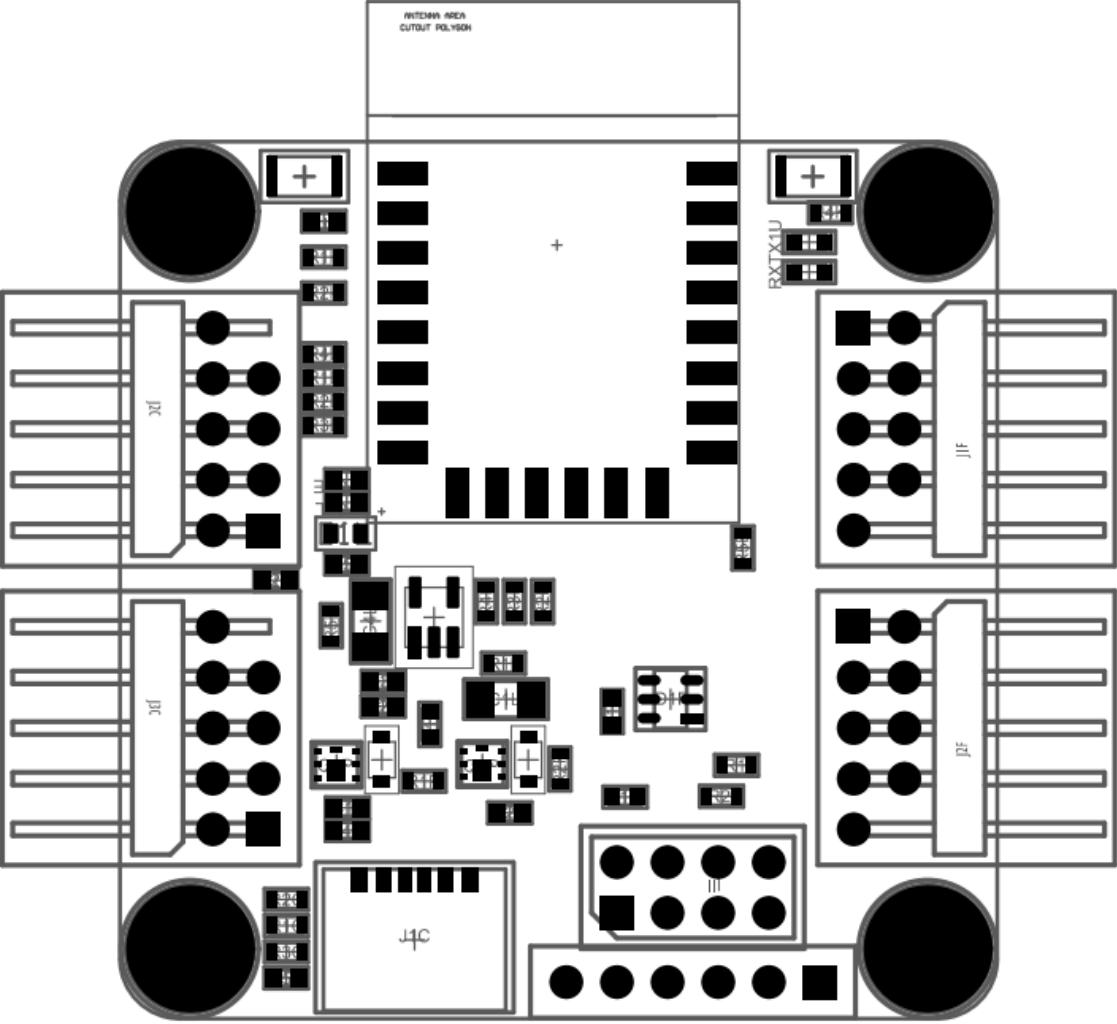
IC1 E



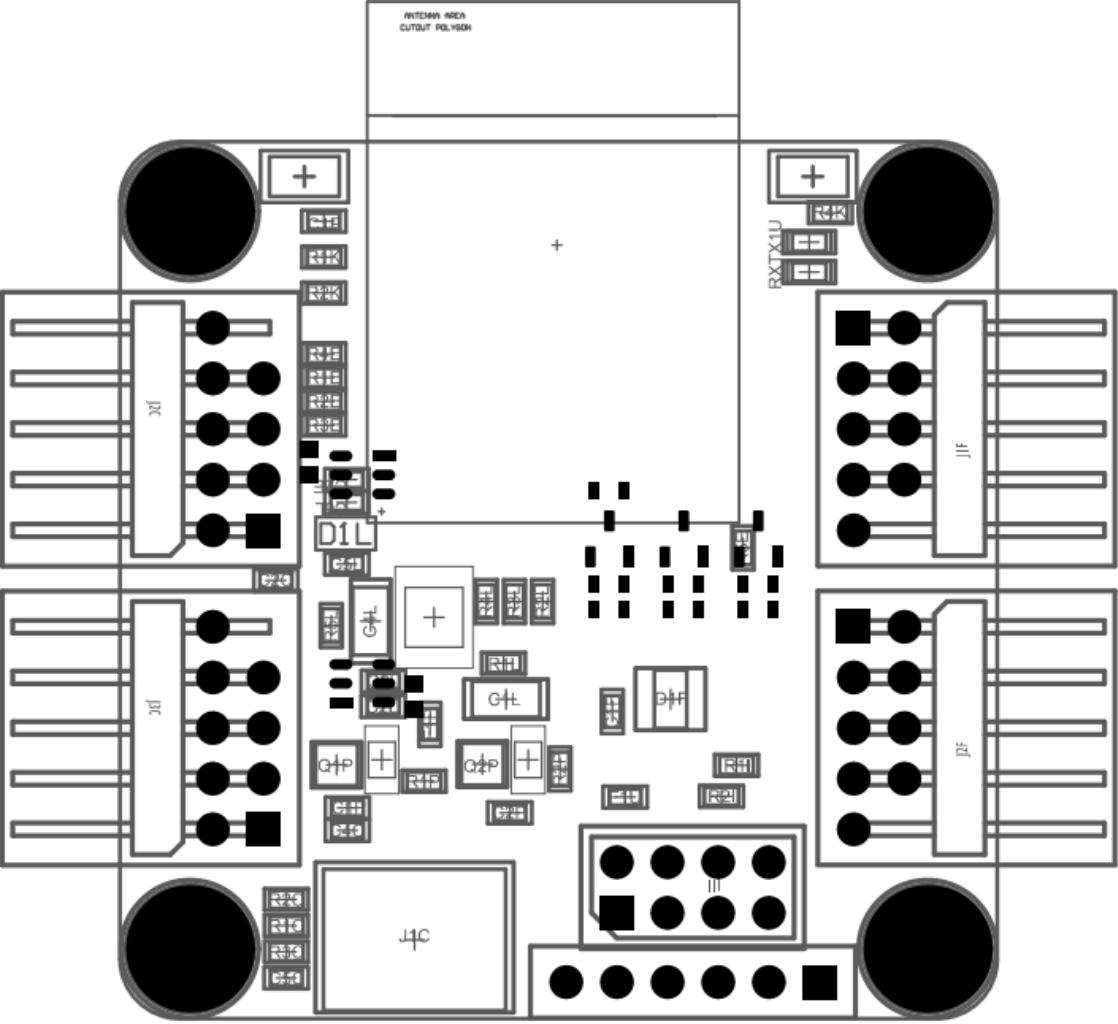
ANTENNA AREA
CIRCUIT BOARD

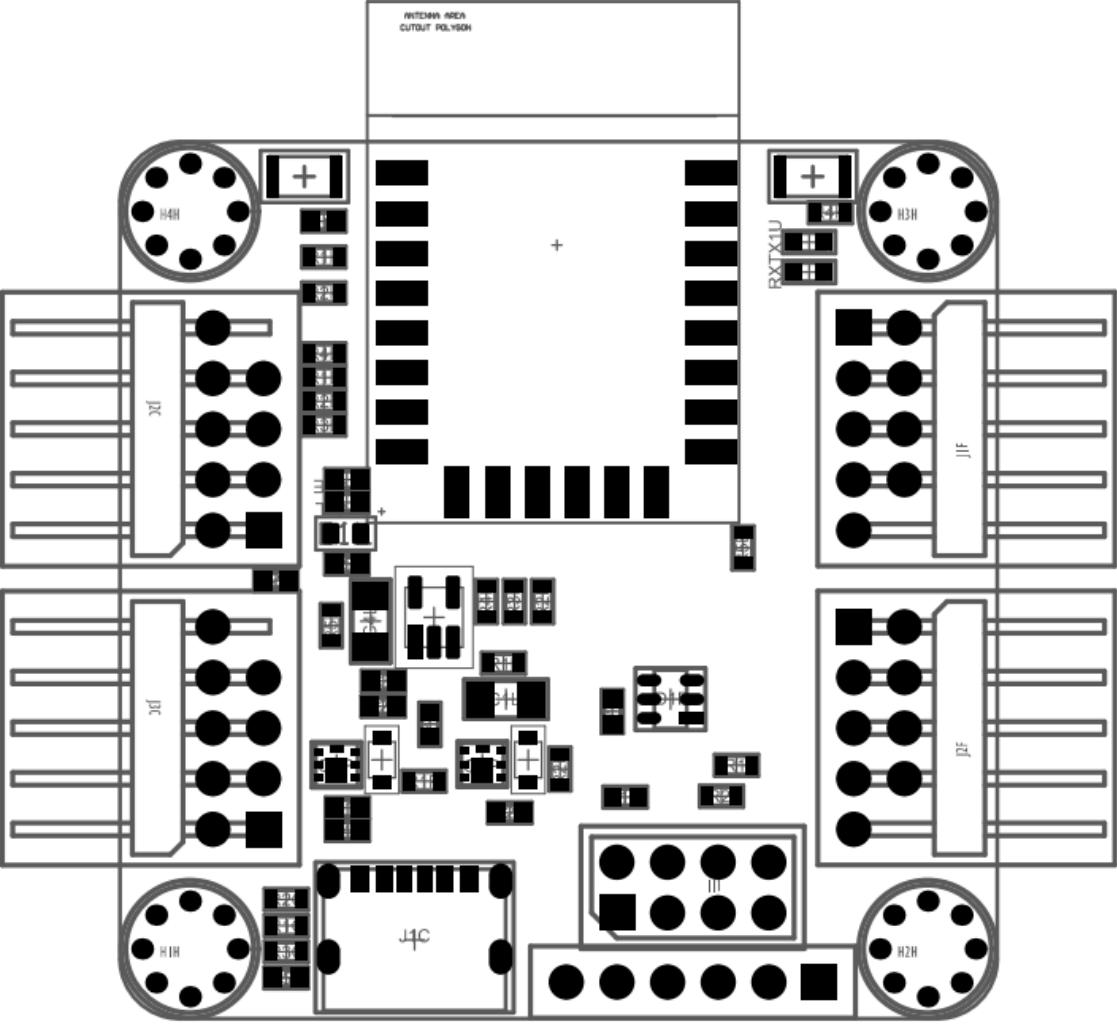


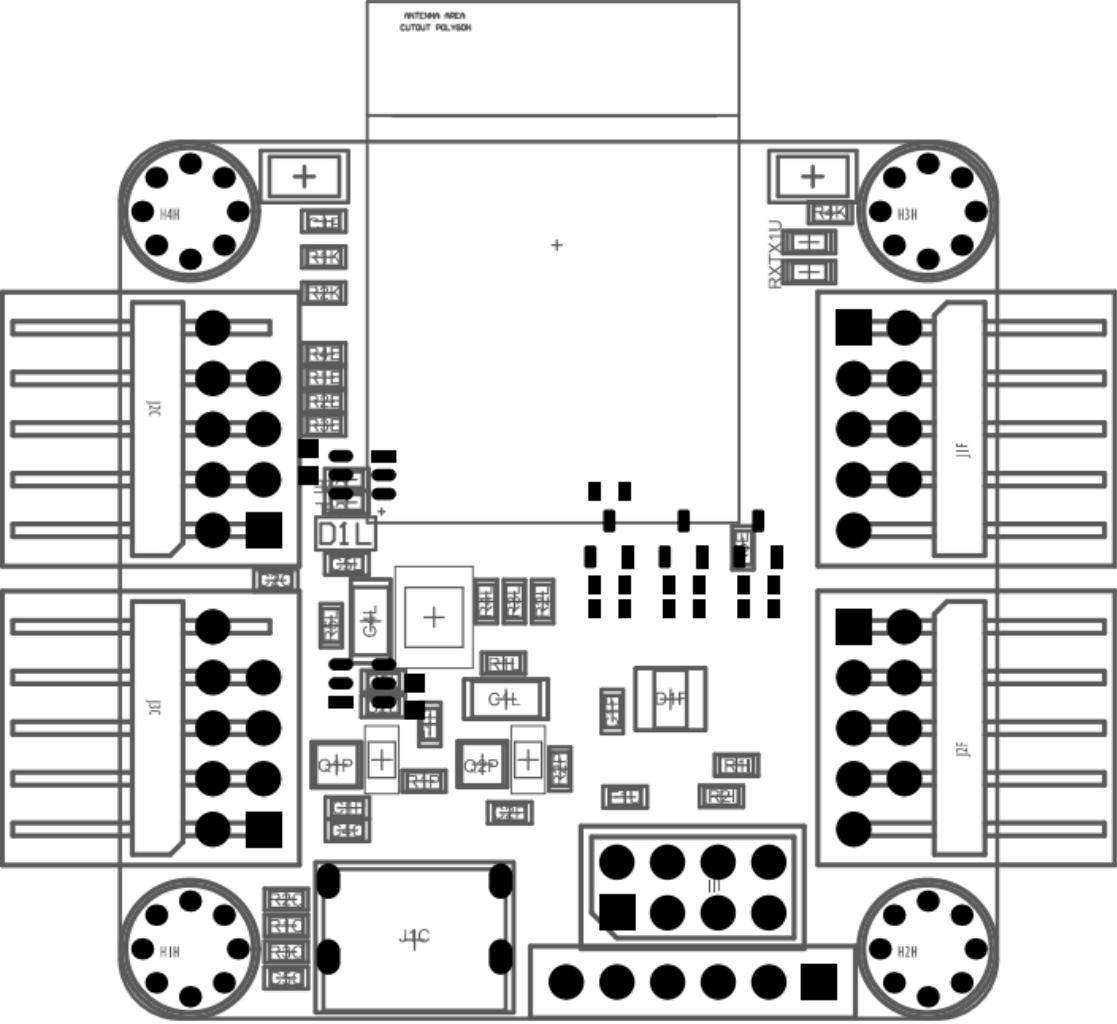


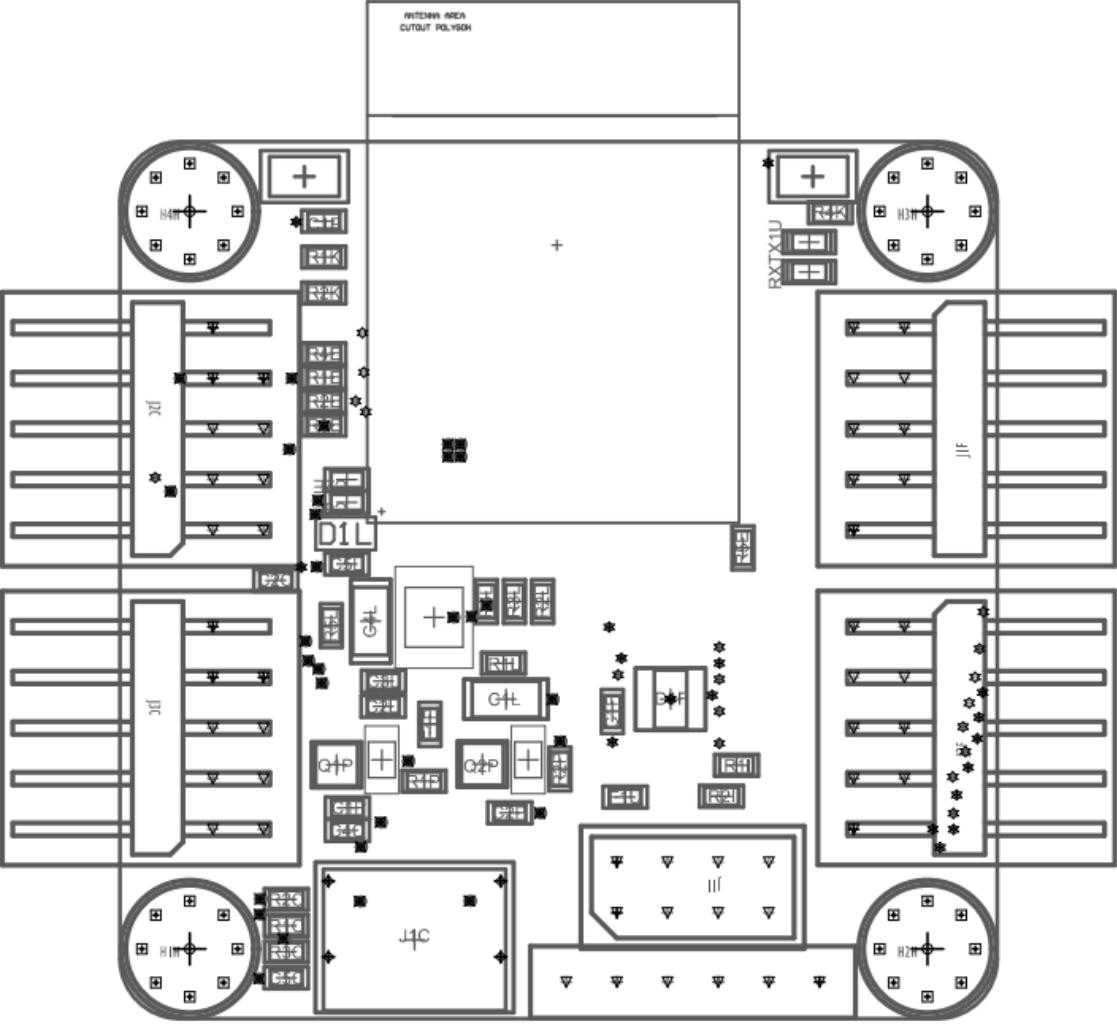


ANTENNA AREA
CUTOUT POLYGON

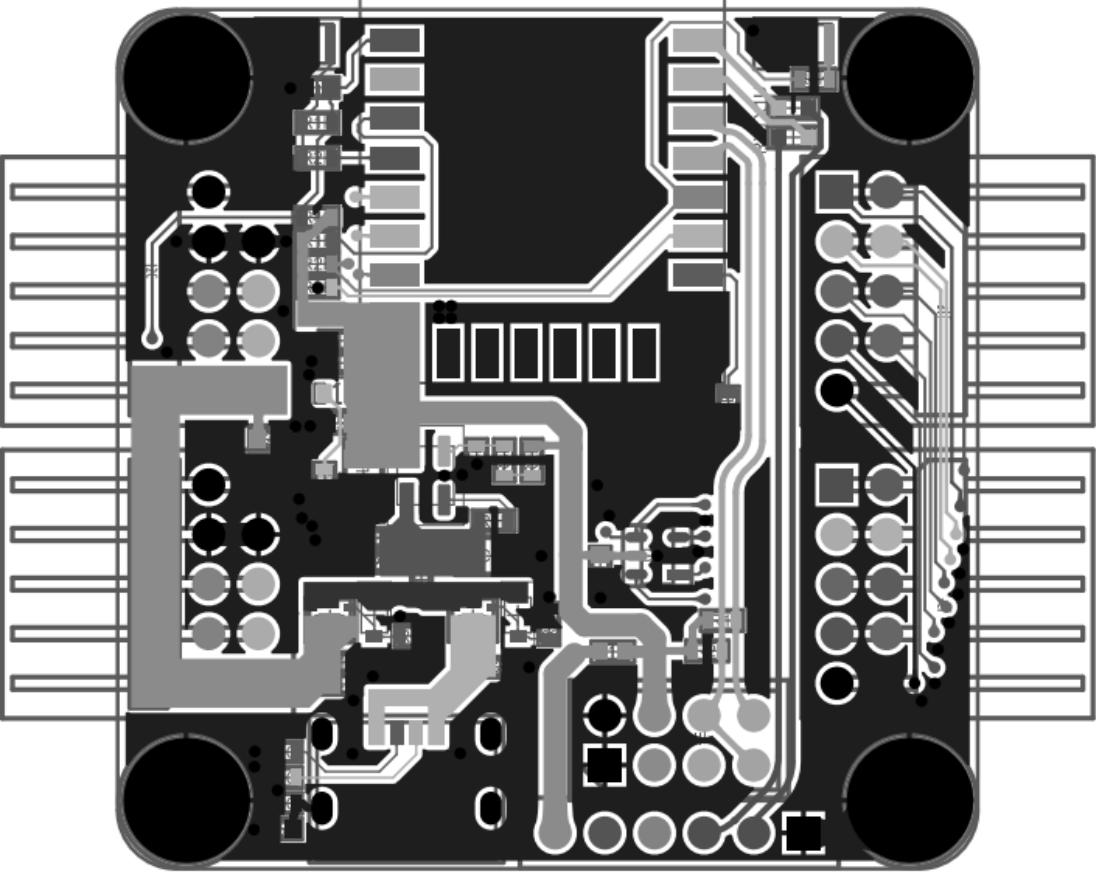




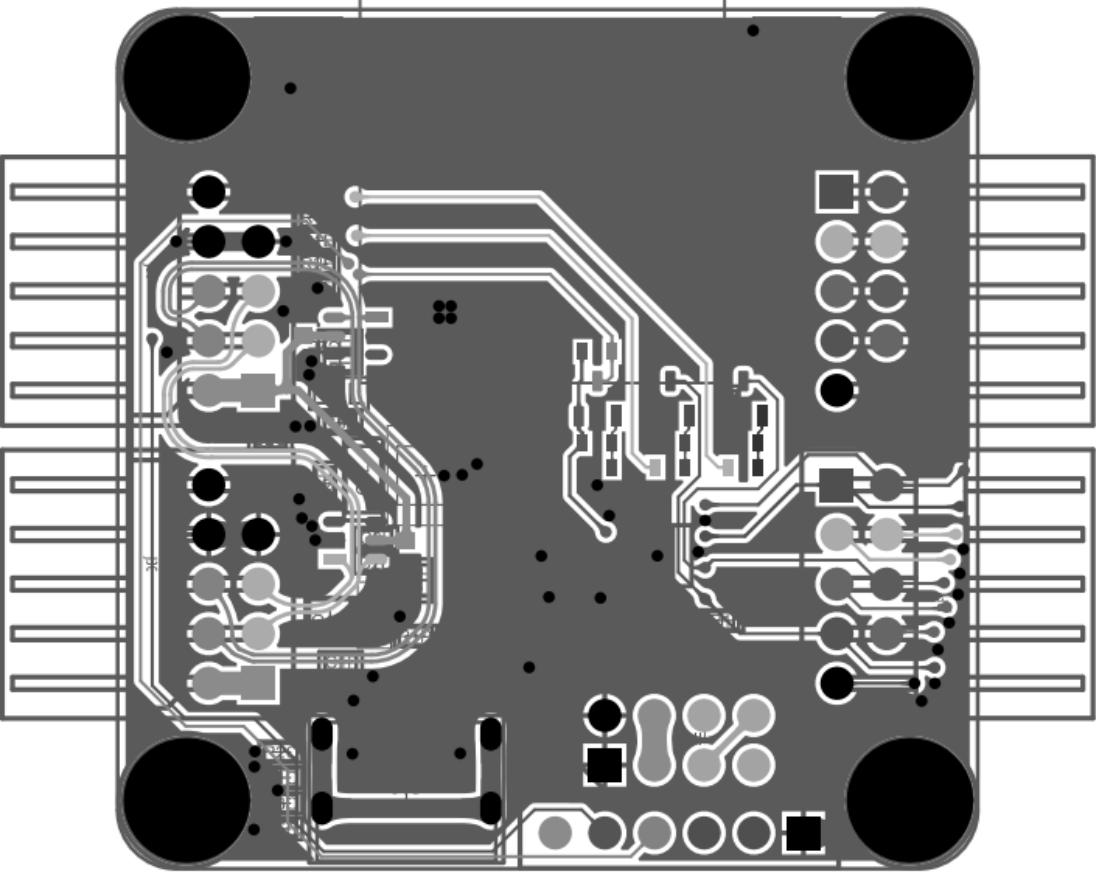




ANTENNA AREA
CUTOUT POLYGON



ANTENNA AREA
CUTOUT POLYGON



IC1 E

ANTENNA AREA
CUTOUT POLYBAG



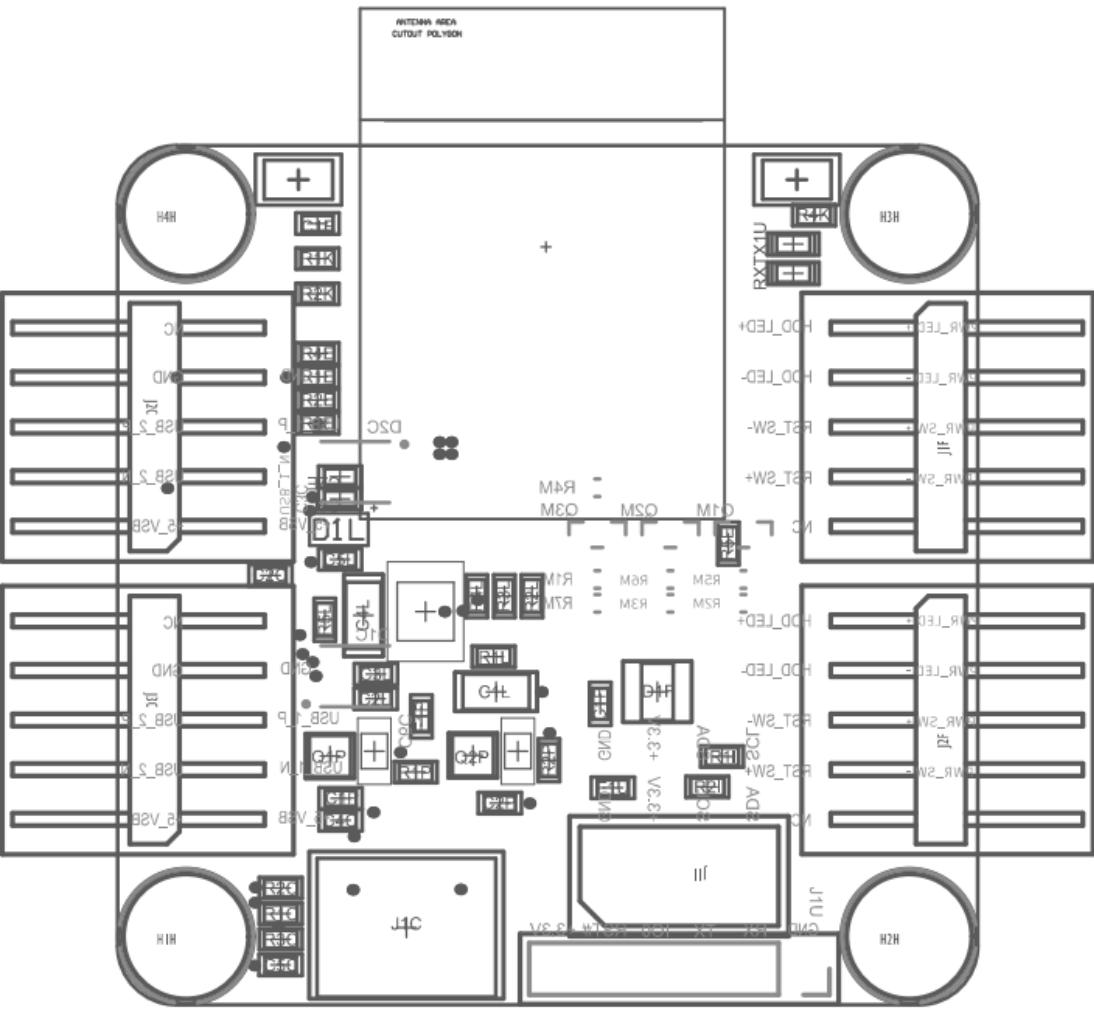
Detailed description: This is a detailed schematic diagram of the R2KONP module. It features a central integrated circuit (IC) labeled 'R2KONP' with various pins labeled. Surrounding the IC are several resistors (e.g., R4B, R2B, R1C), capacitors (e.g., C2E, C1G), and other electronic components like diodes and transistors. The module is mounted on a printed circuit board (PCB) with various pads and connection points.

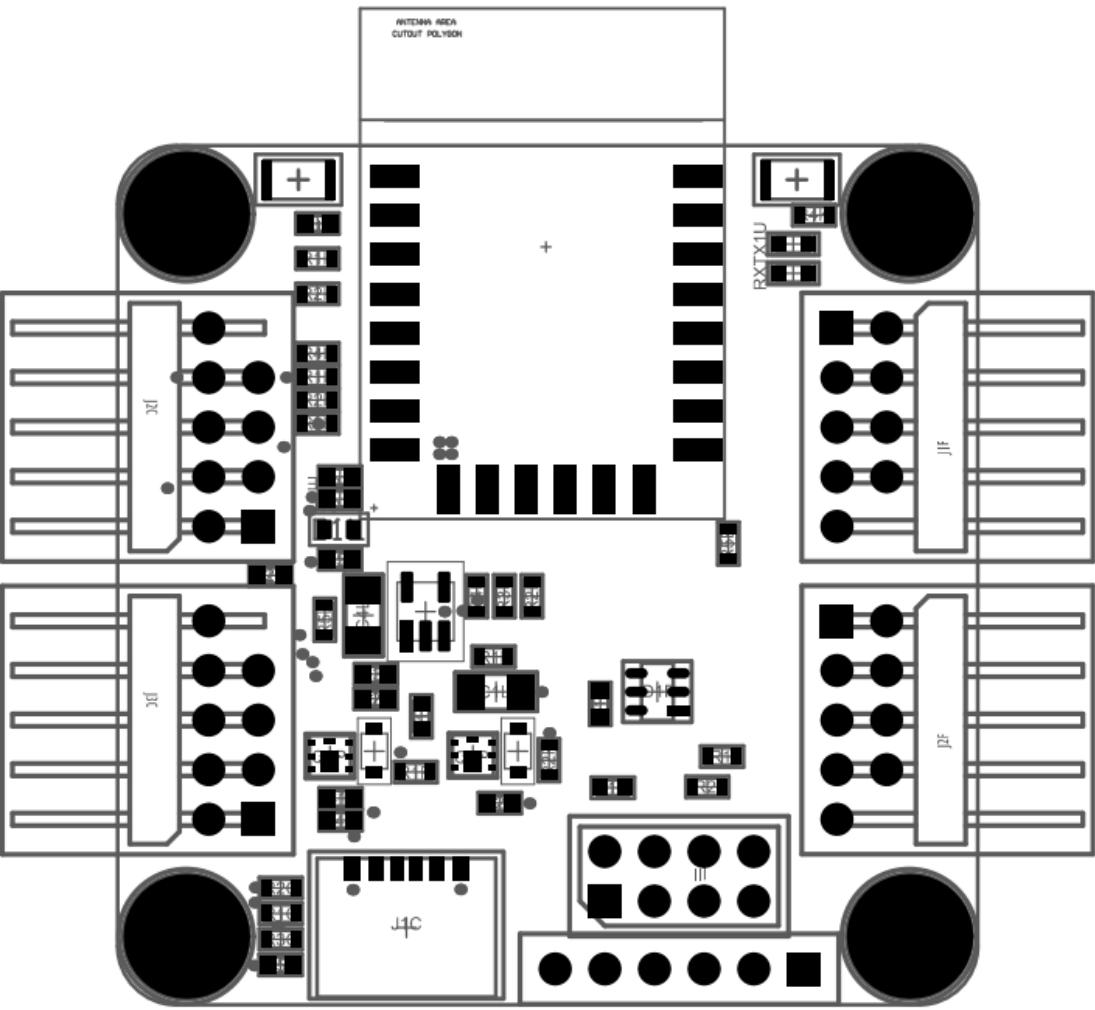
A circular component with a central hole and four rectangular pads arranged vertically on its right side. The pads are labeled R1C1, R1C2, R1C3, and R1C4 from top to bottom.

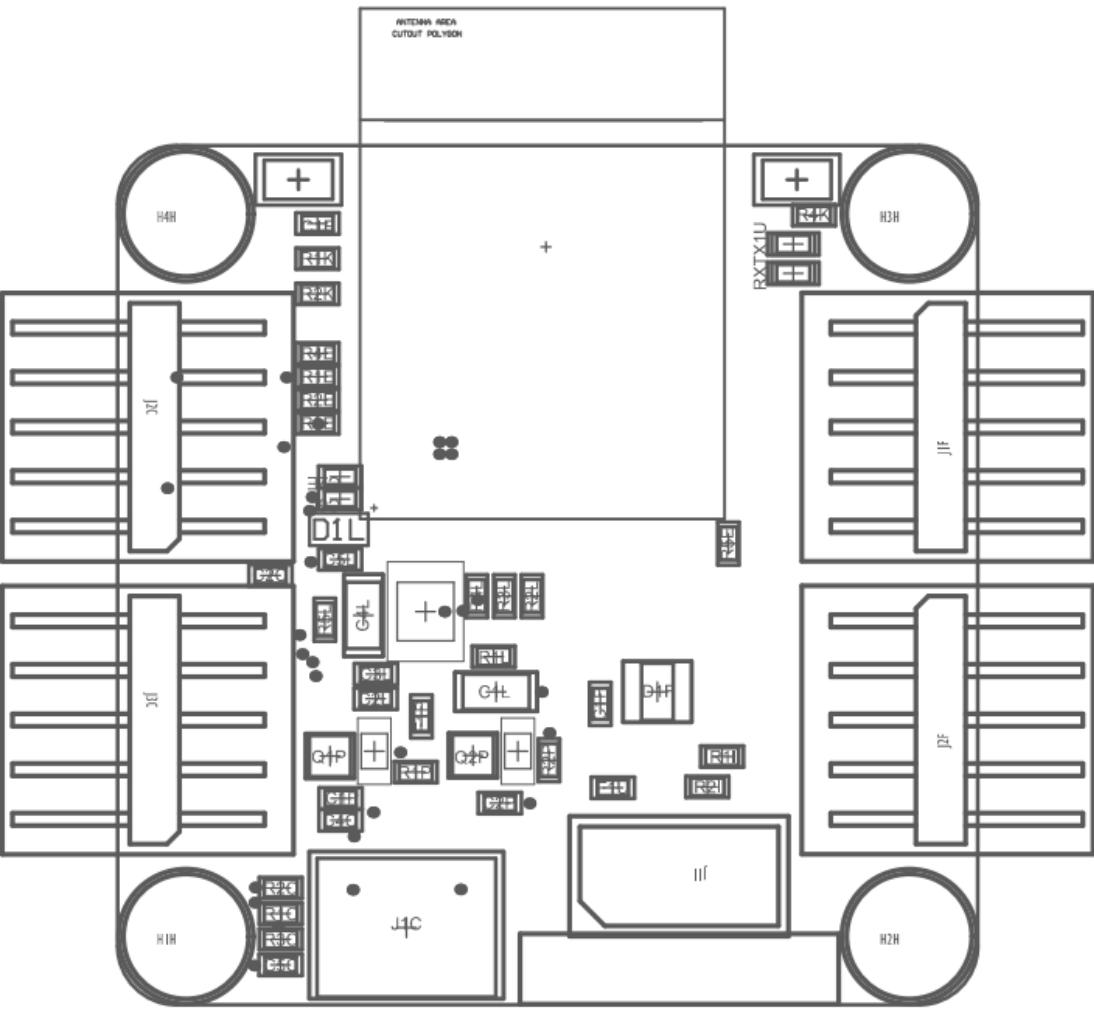
R20
@

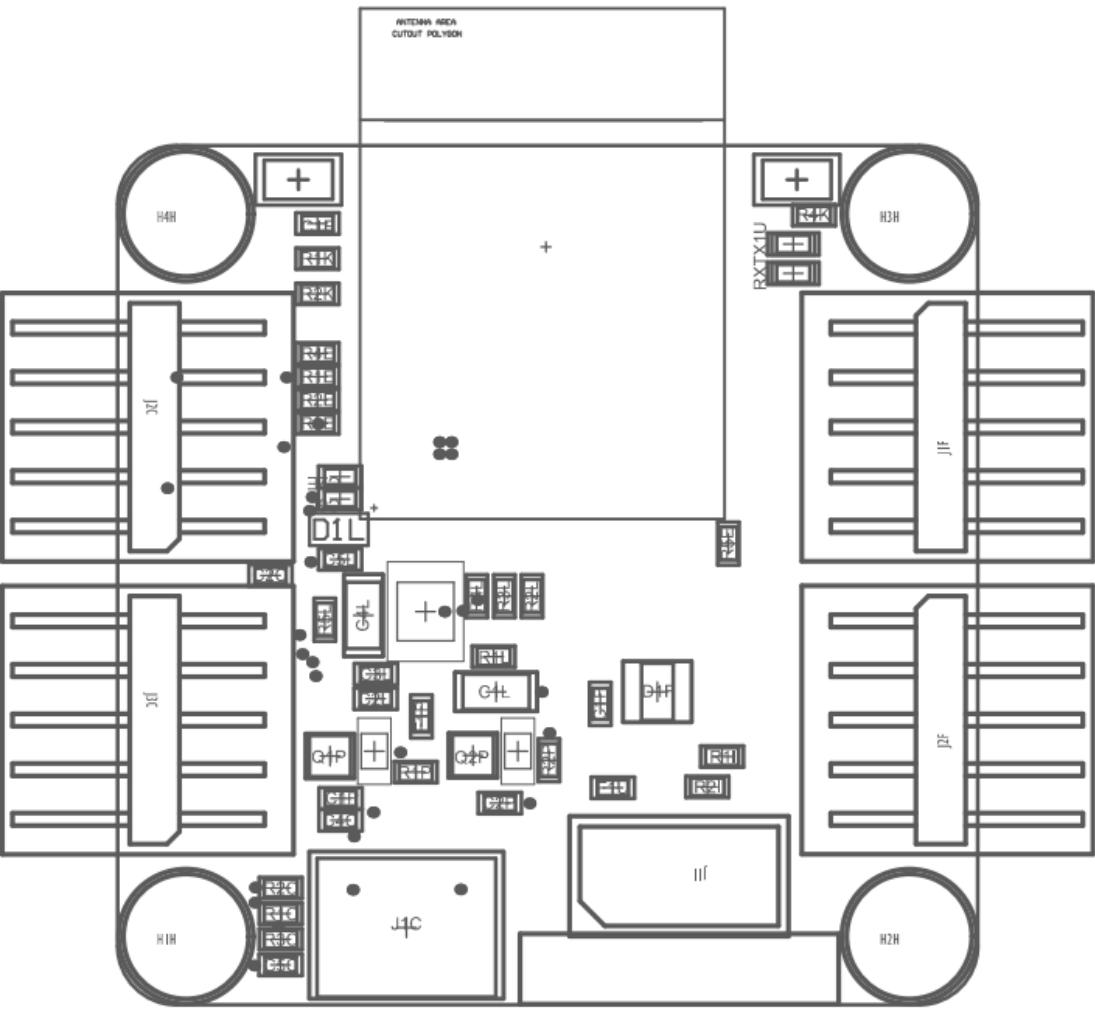
The image shows the front panel of a server chassis. On the left, two vertical ports are labeled "R11" and "R21". To the right of these ports is a vertical stack of six horizontal slots, each containing a black metal plate with a small circular hole near the top.

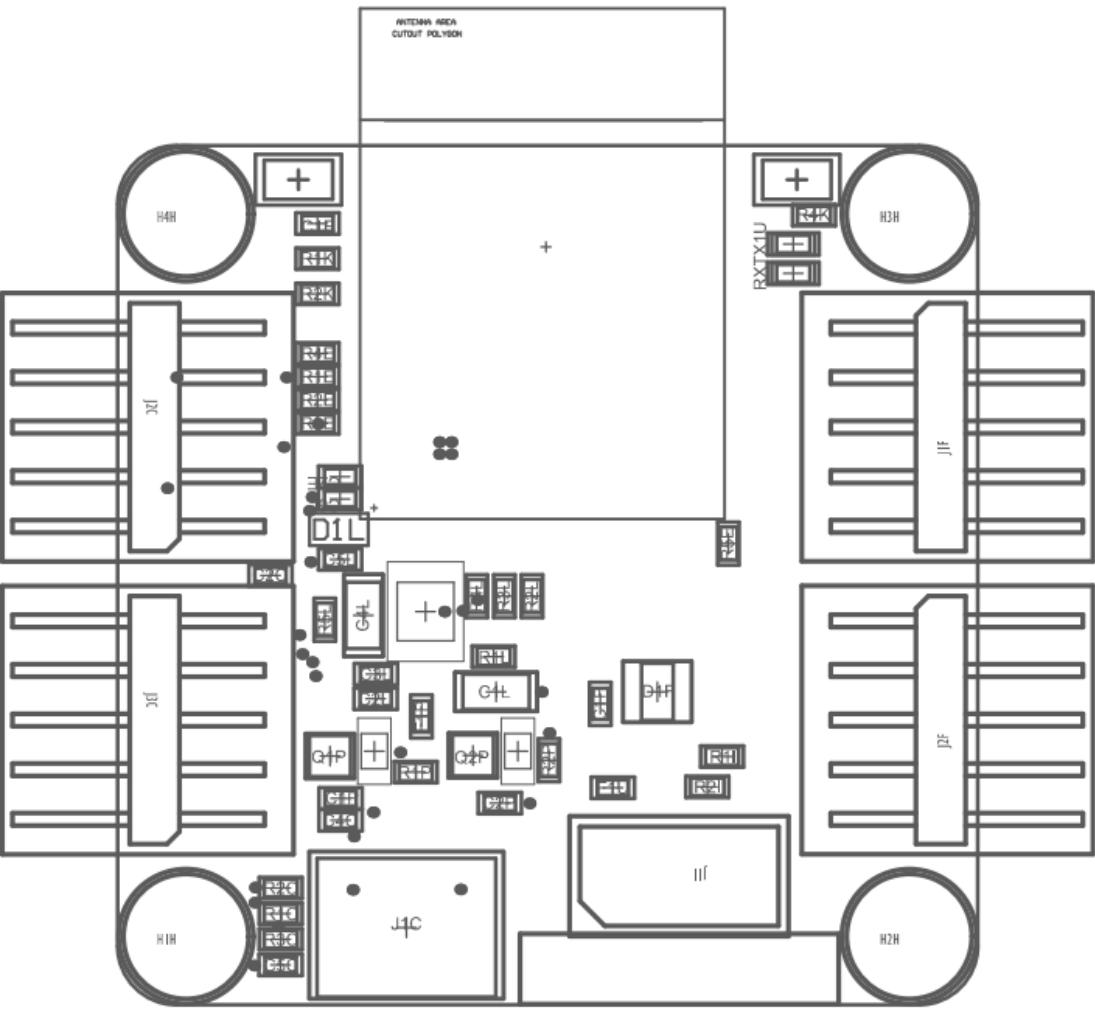
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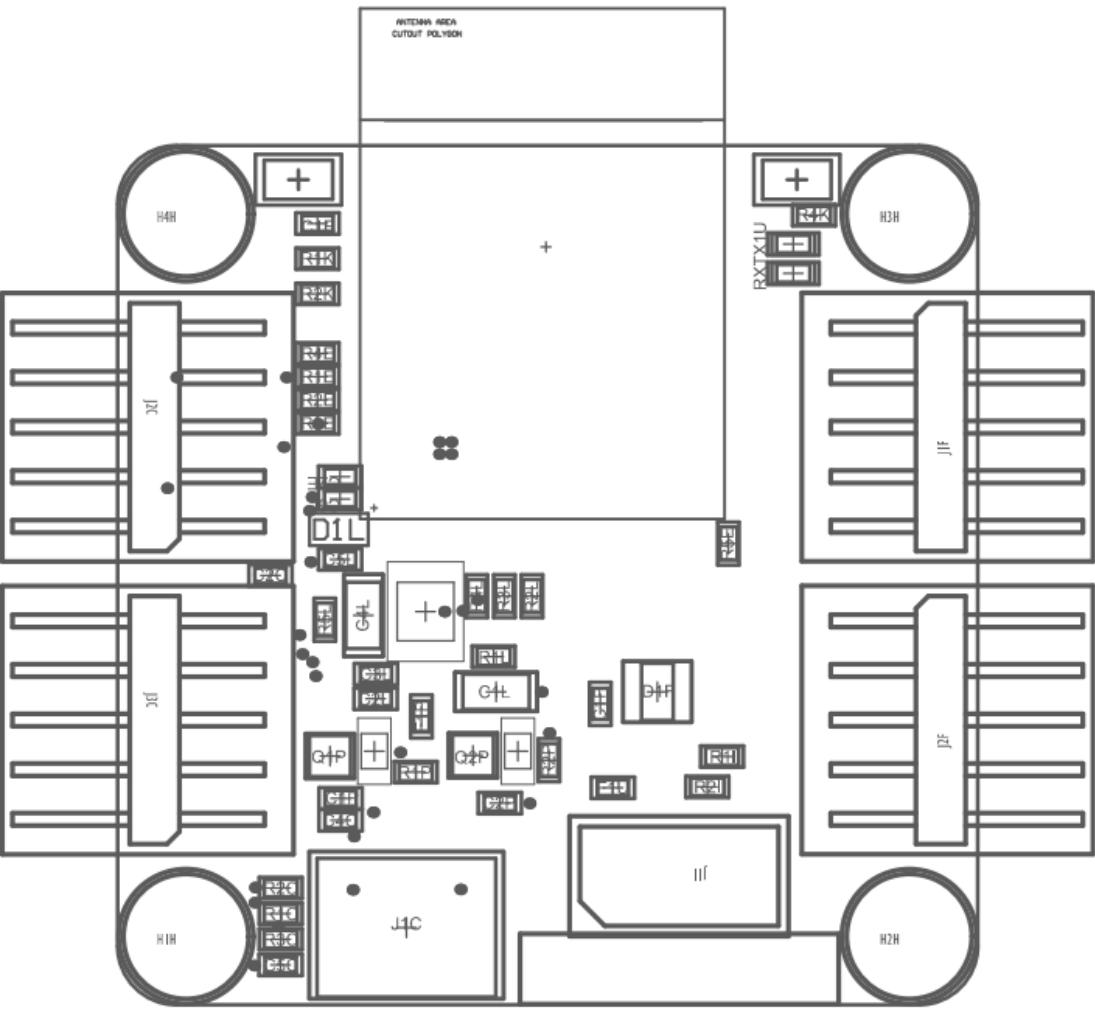


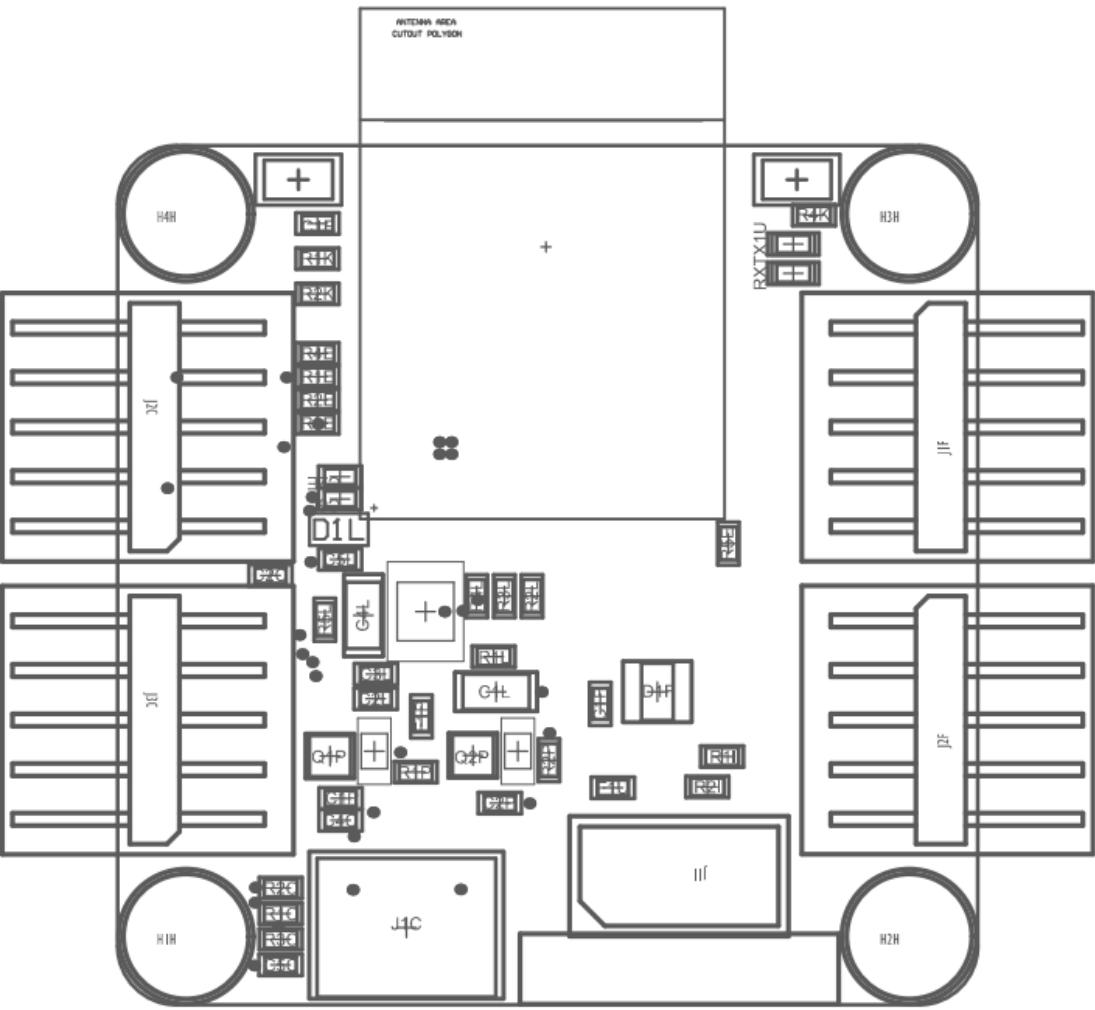


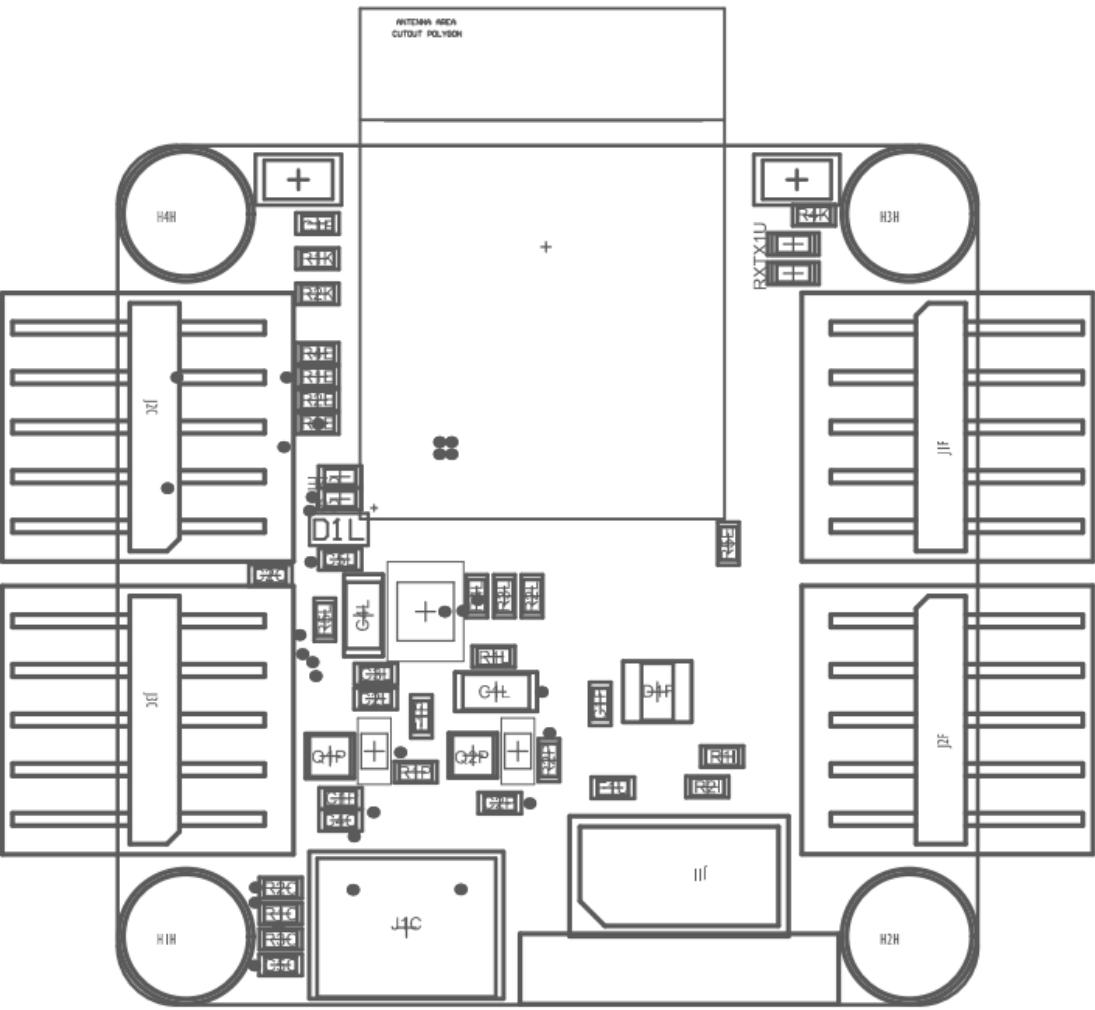


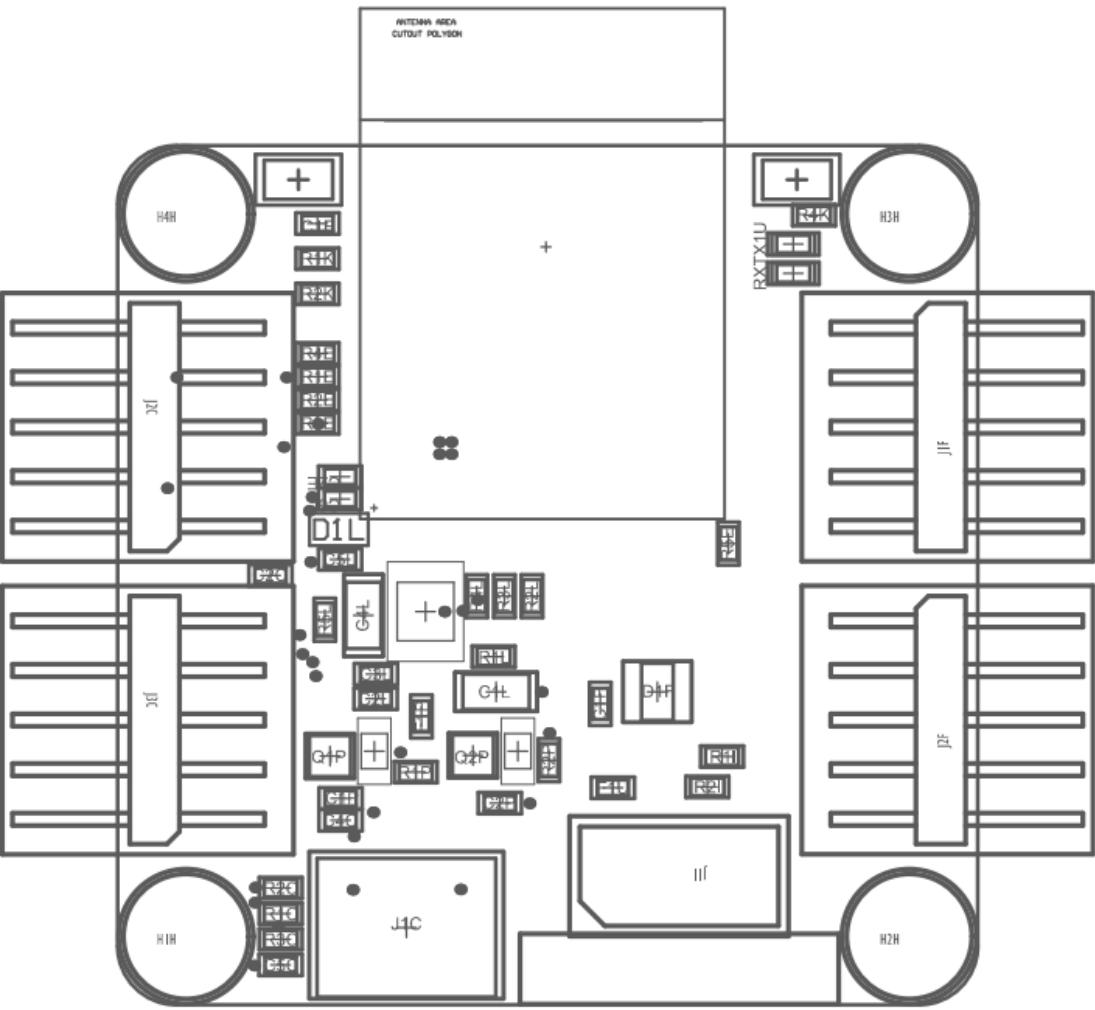


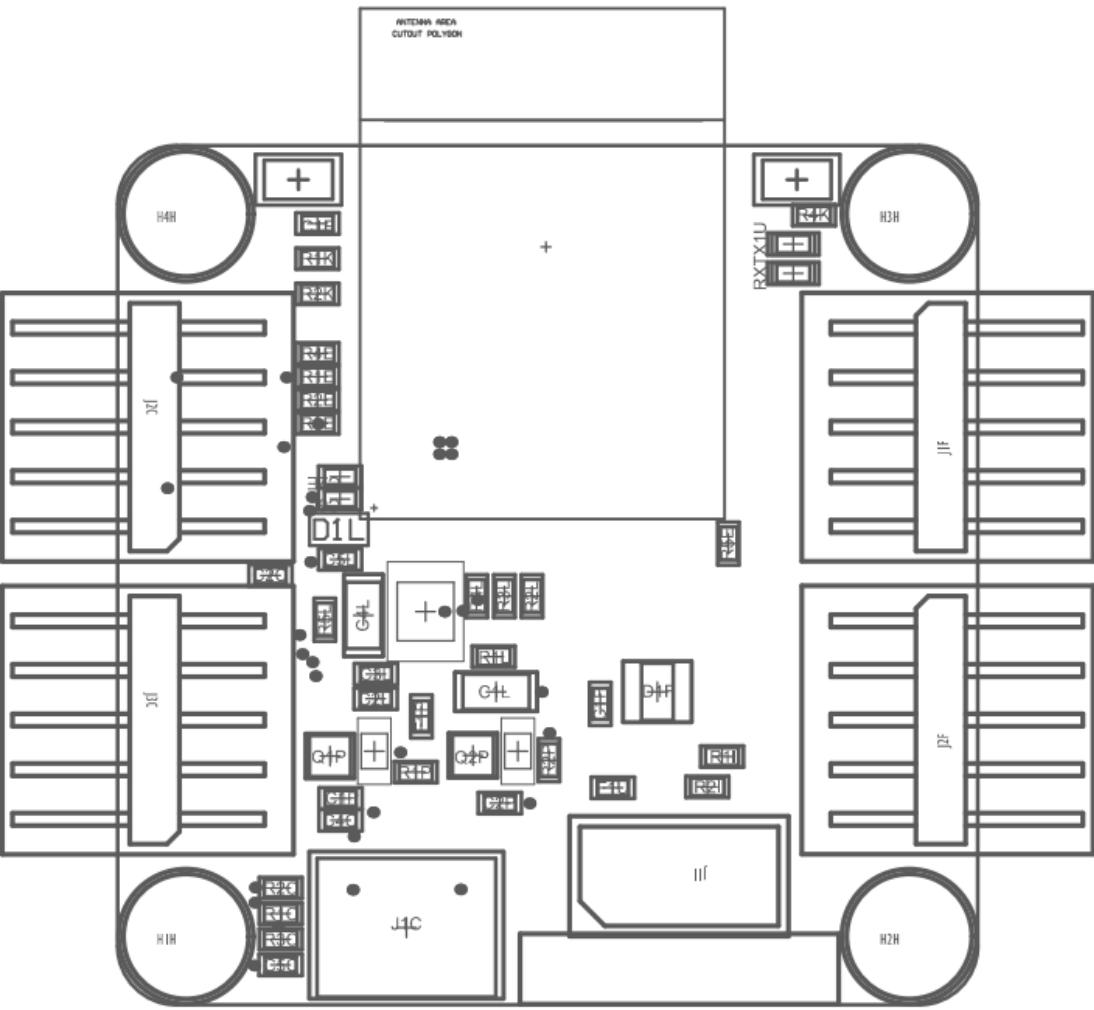


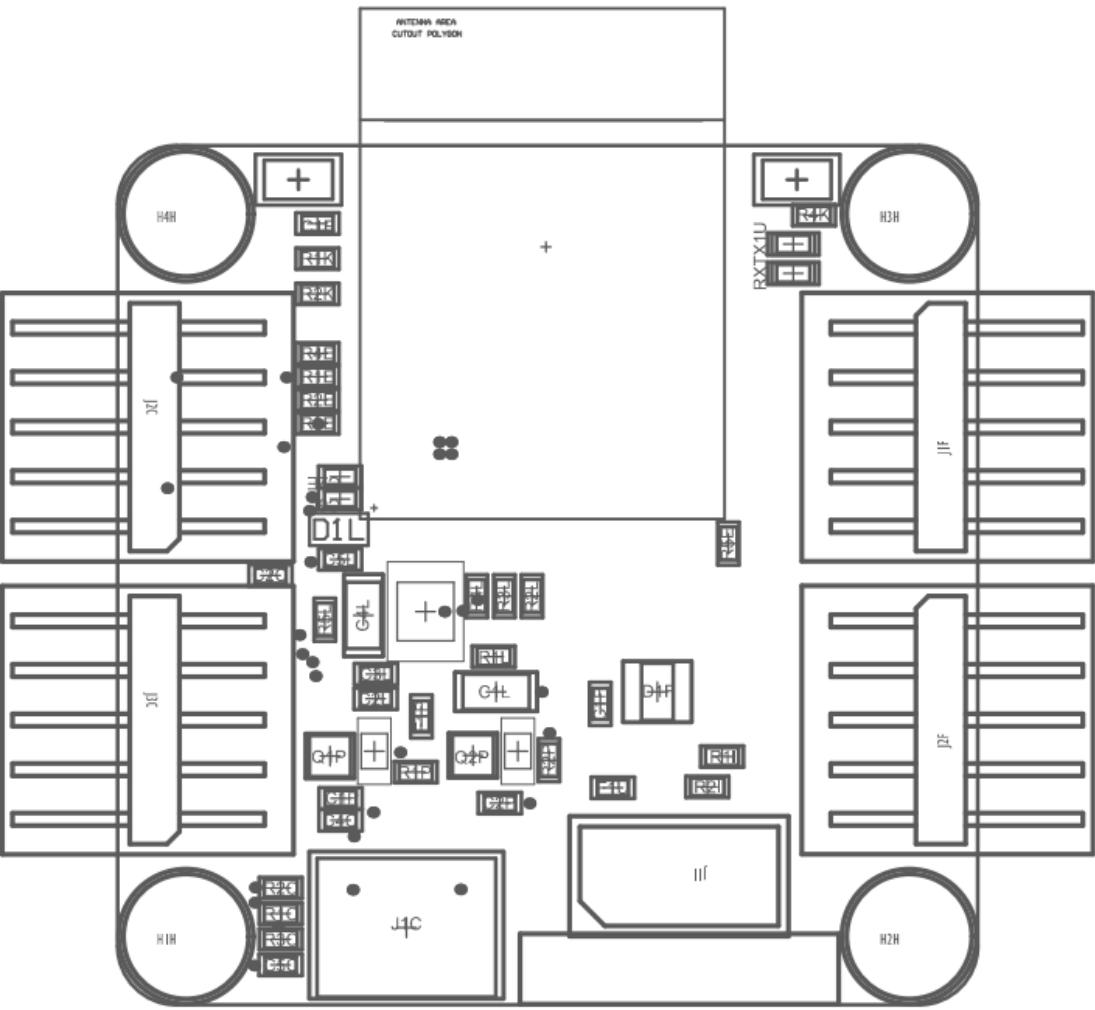


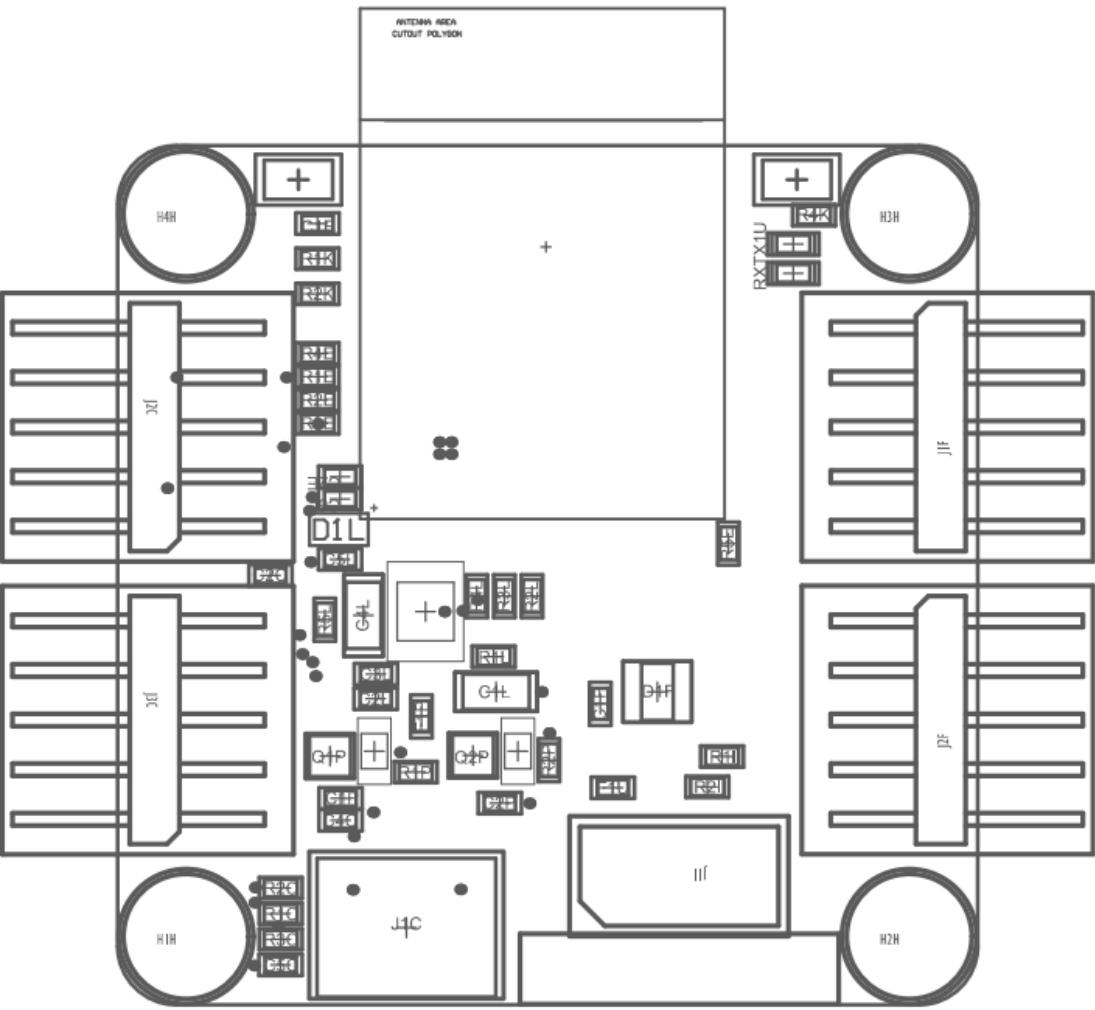


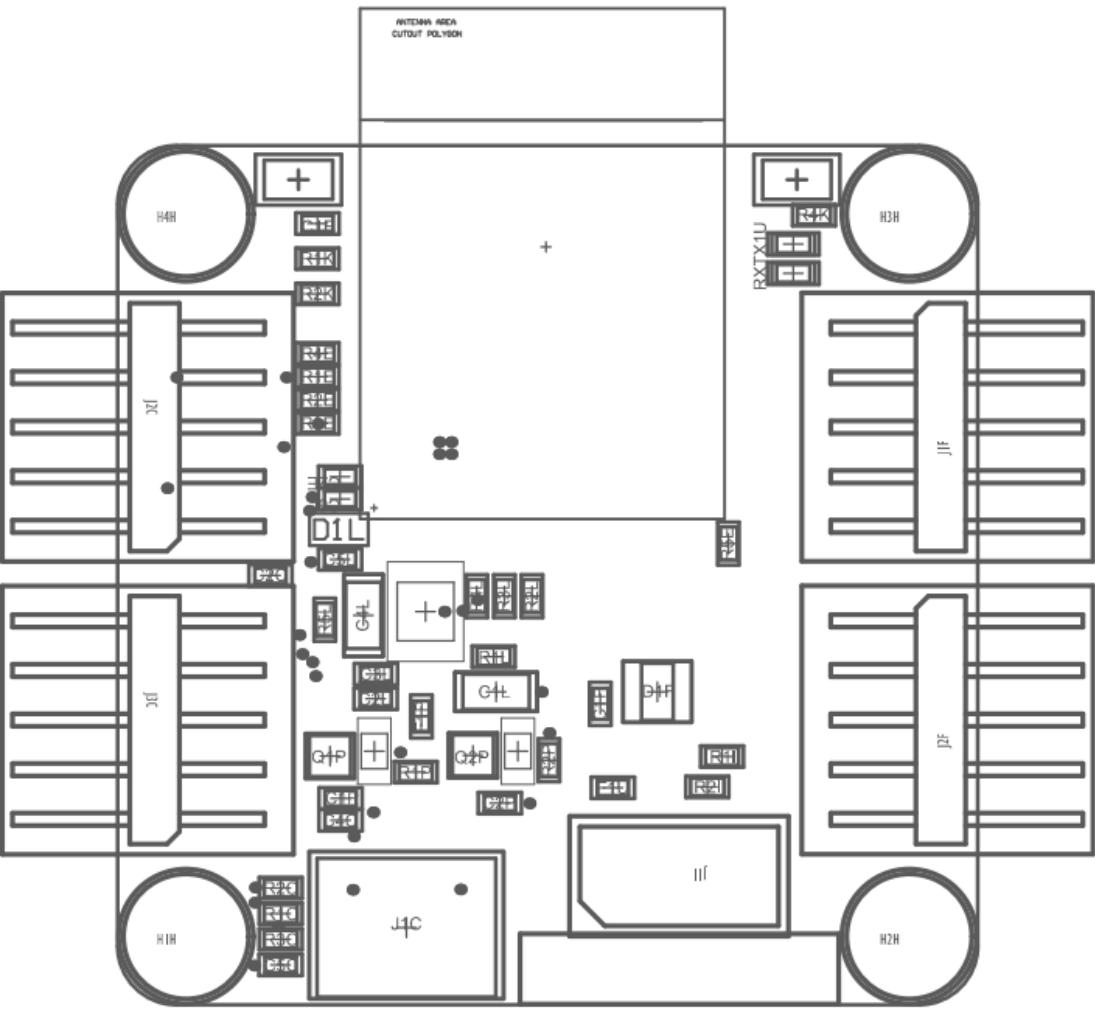


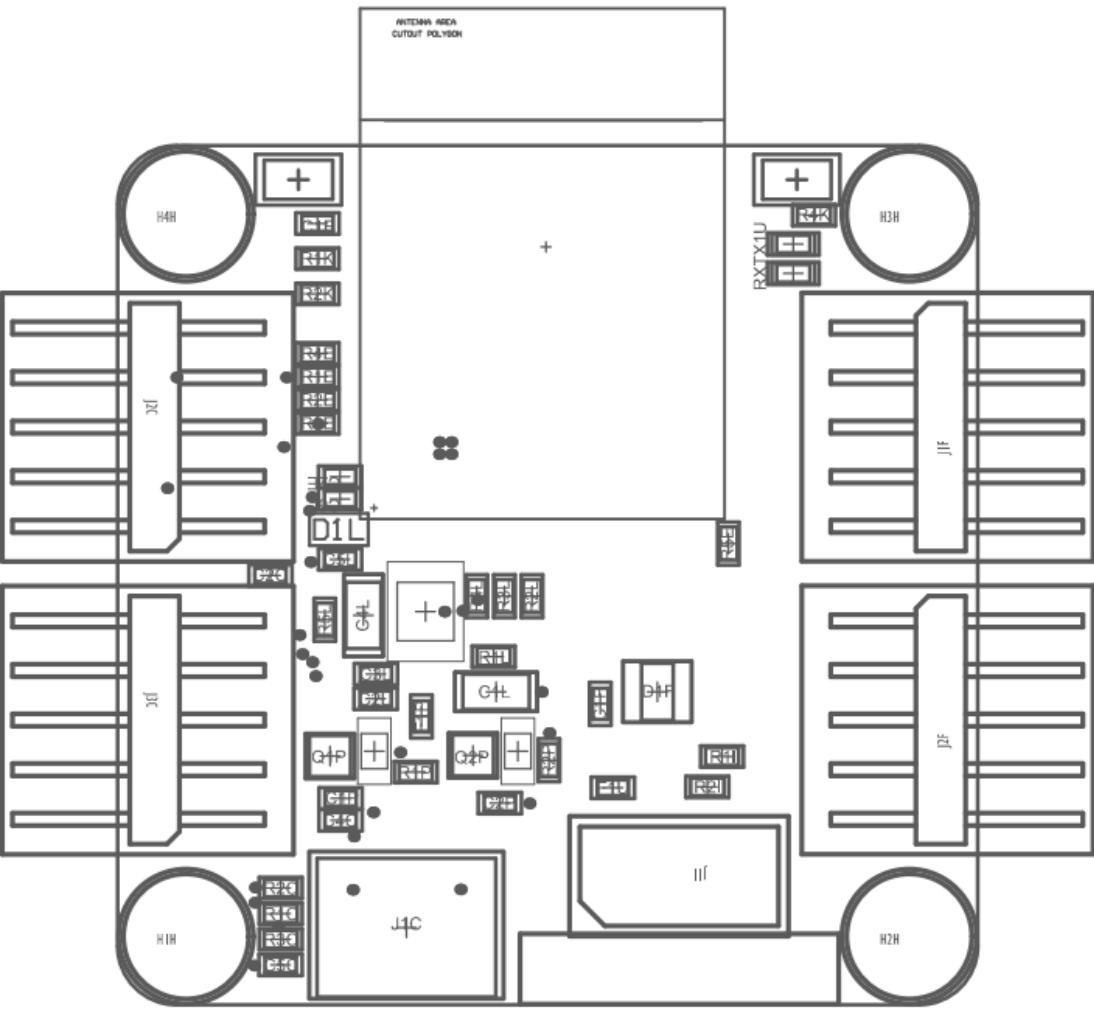


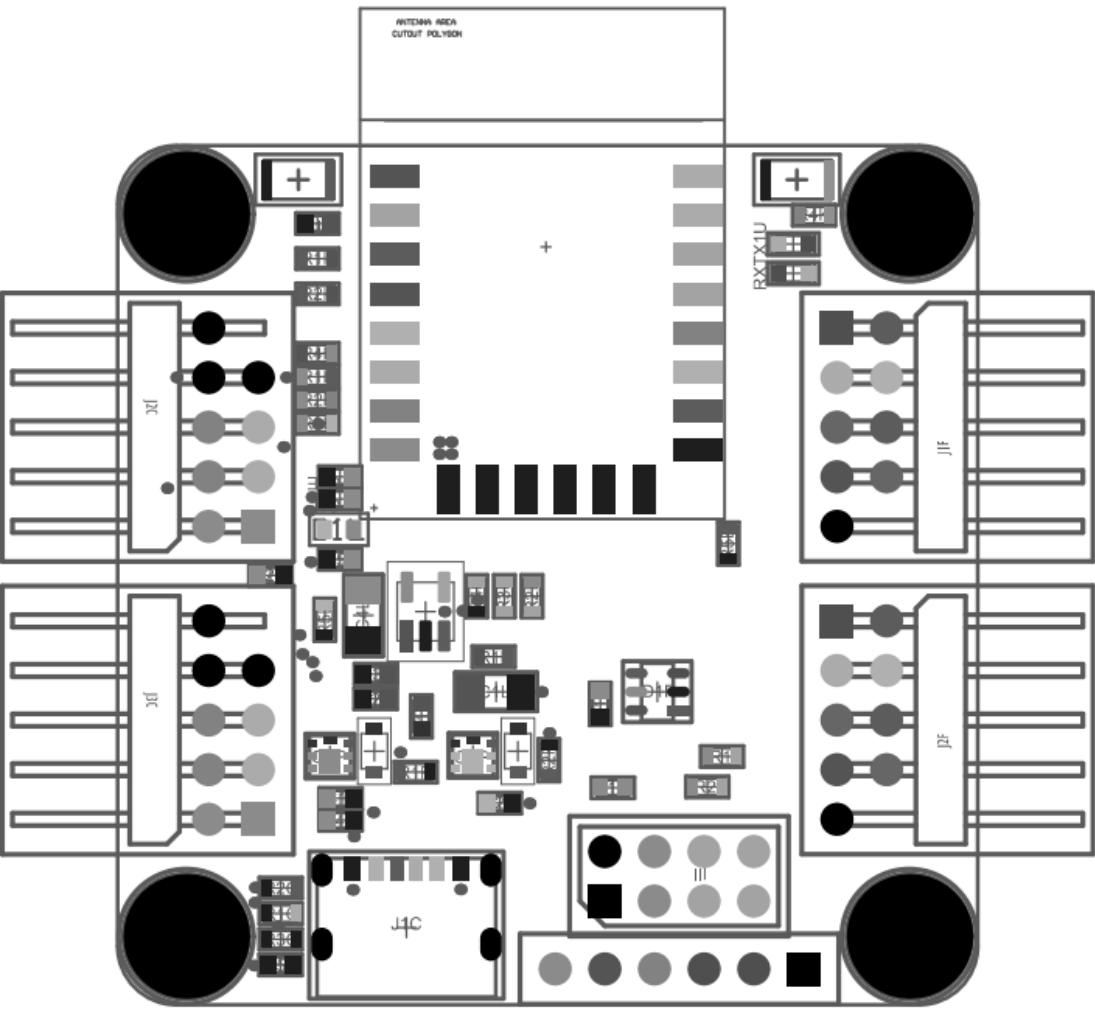


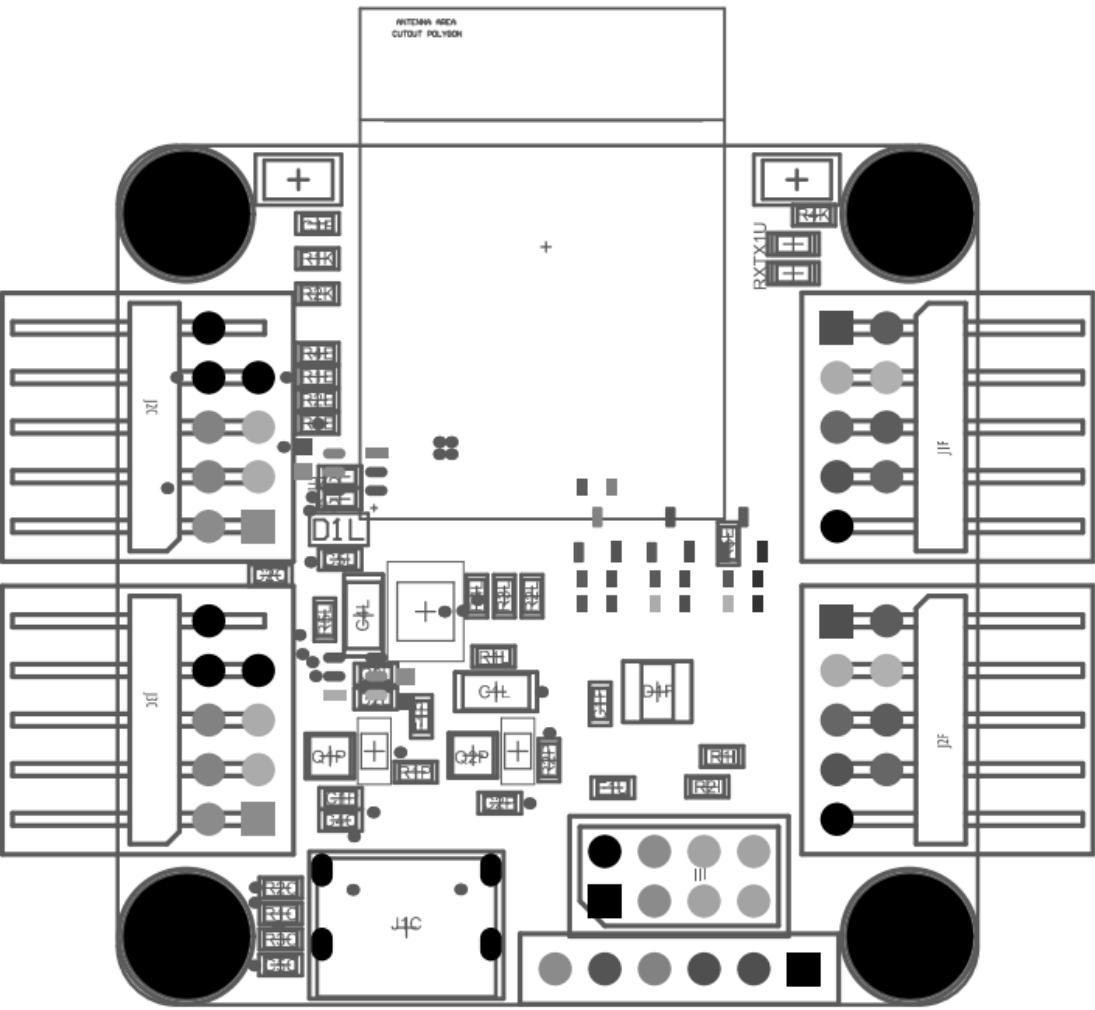


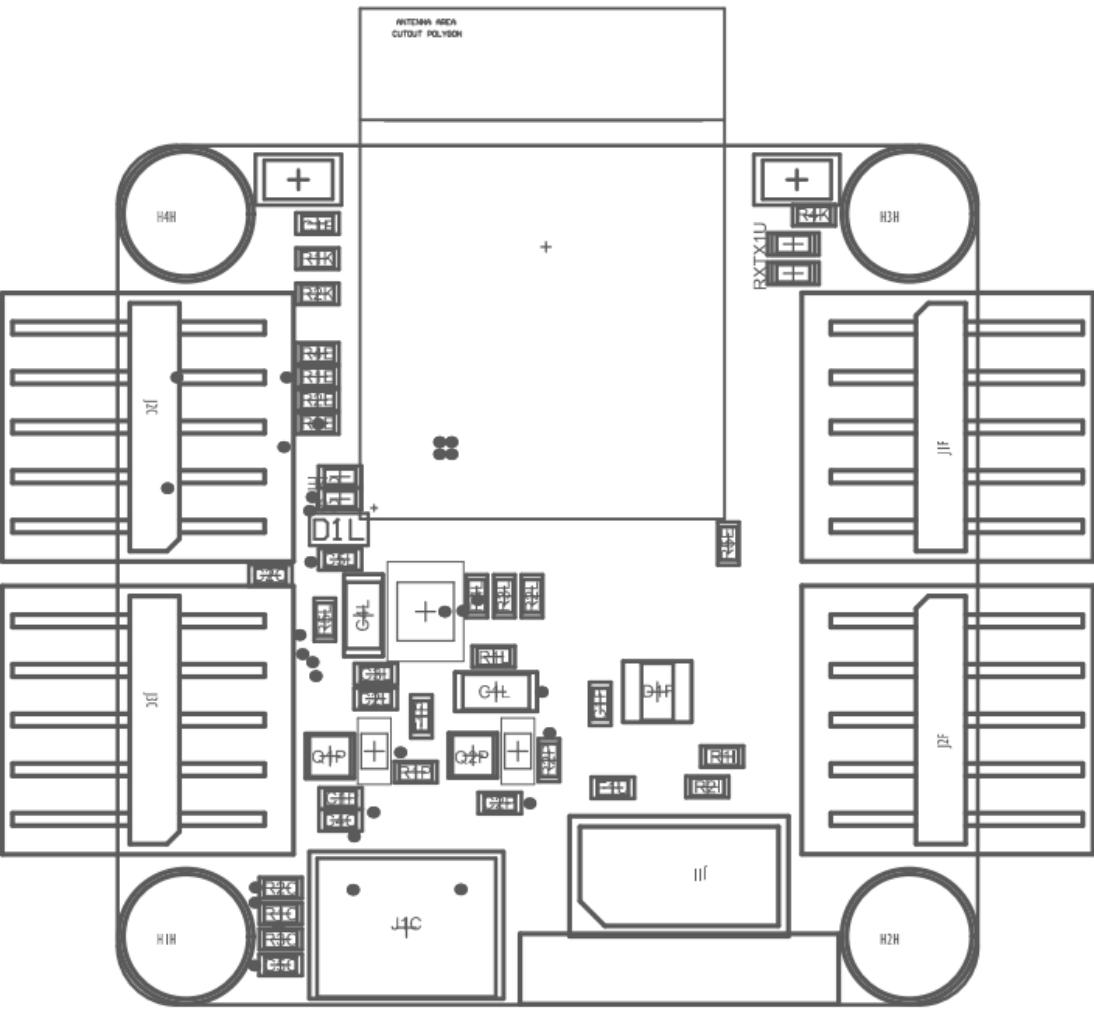


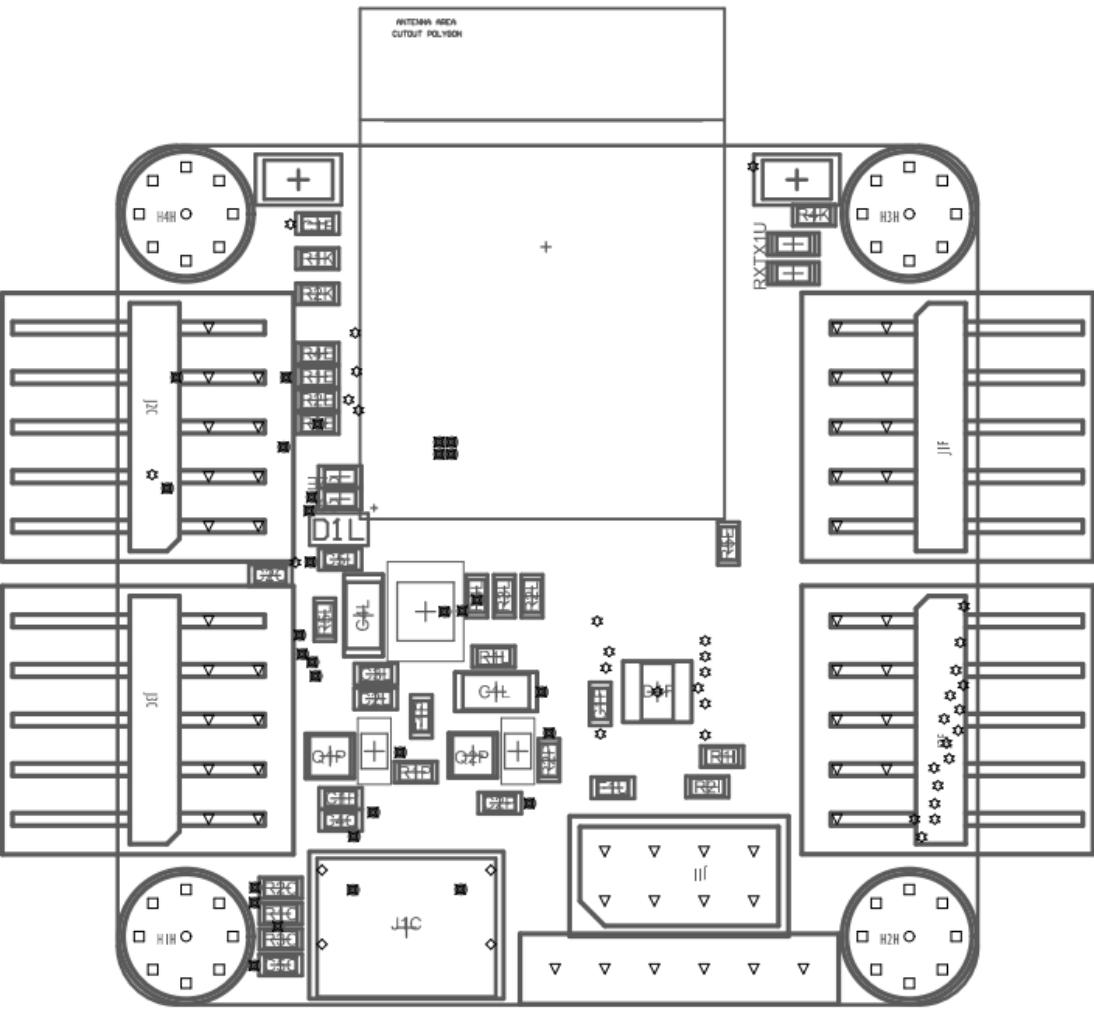












ANTENNA AREA
CUTOUT POLYGON

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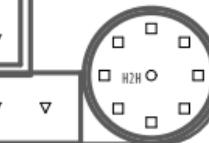
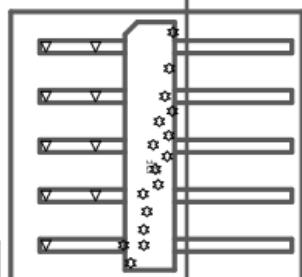
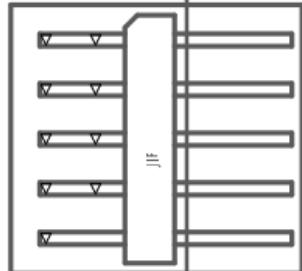
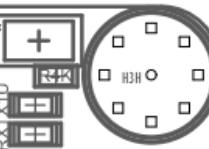
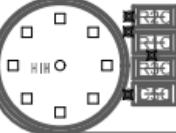
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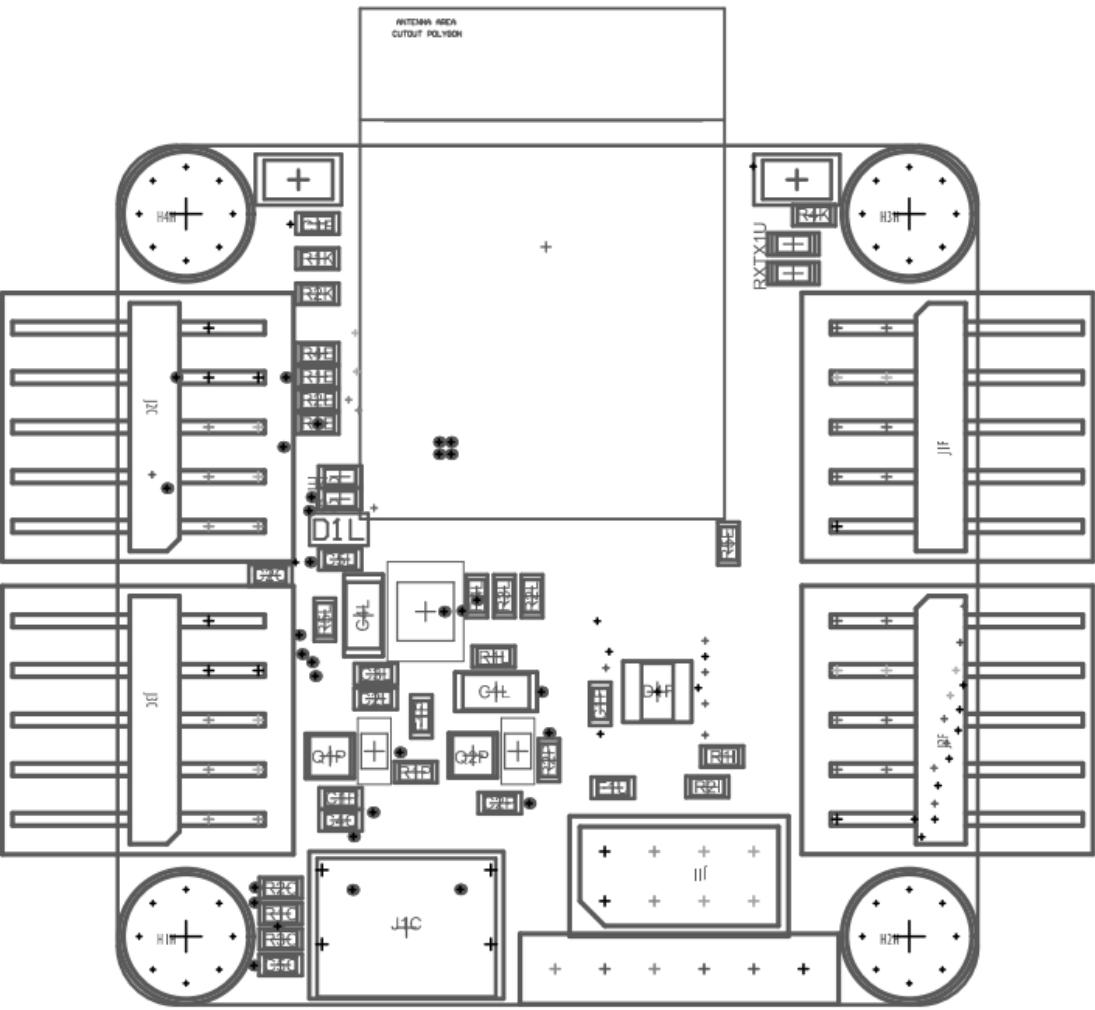
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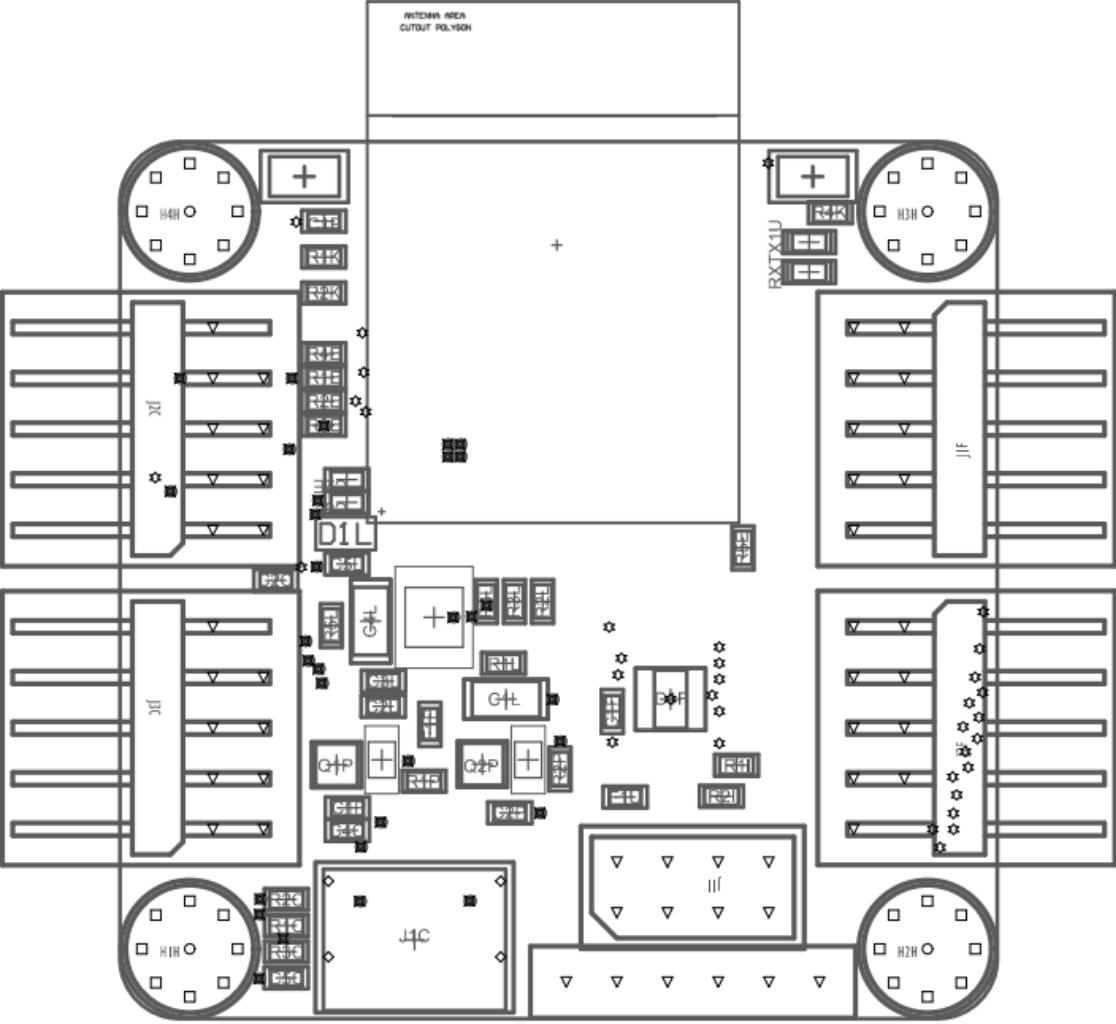
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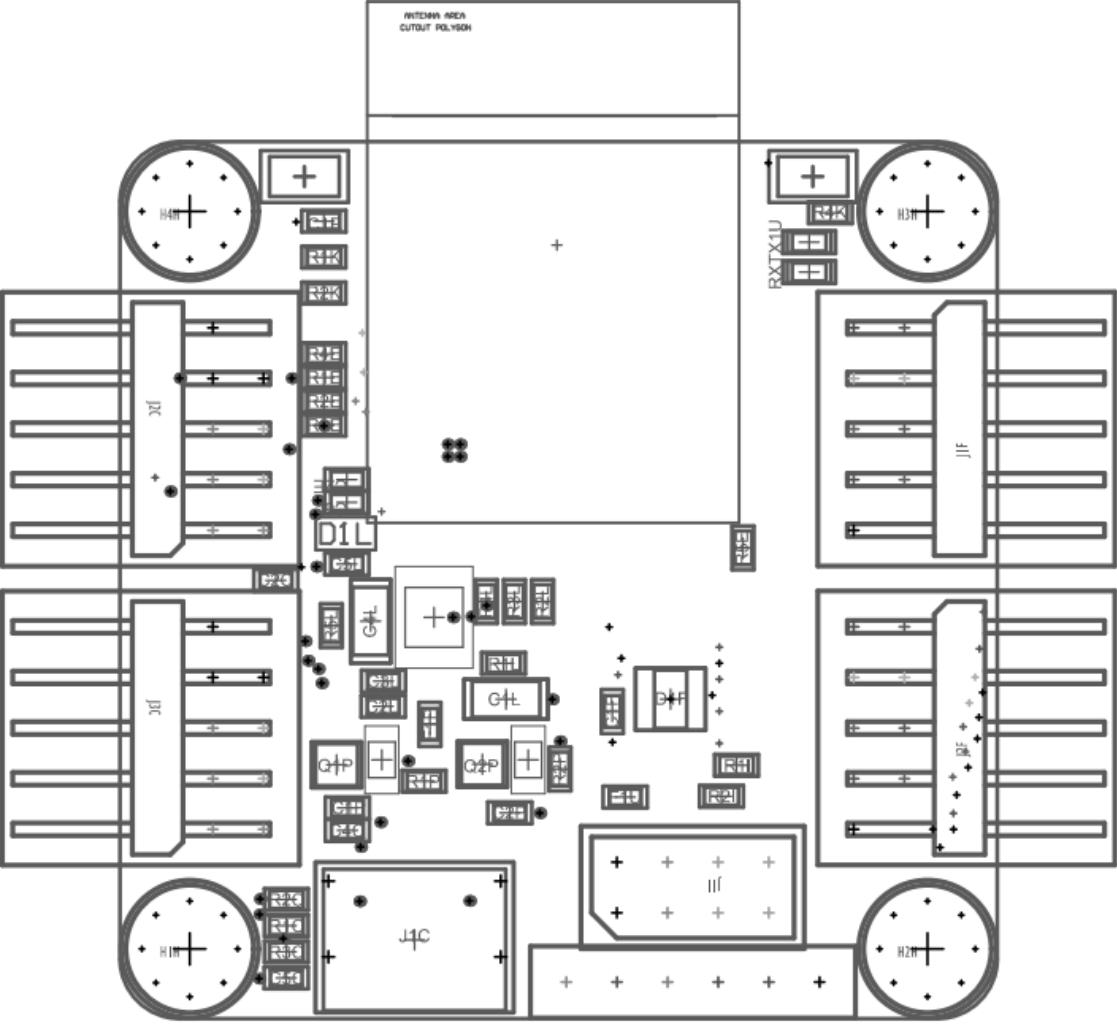
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Comment	Designator	Footprint	LibRef	Quantity	Manufacturer Part Number	Value	Tolerance	Voltage Rating
KGM15AR70J104KM XTR_005	C1E, C2E	CD603-IPC_C_No_Silk	100nF_6_3V	2	KGM15AR70J104K M	100nF		
CD603C10K9RACUTL Capacitor, 0.1uF, 10V, ± 10%, XTR, 0603 [1608 Metric]	C1F, C1P, C2P, C3C, C3L, C5C, C6C	CD603-IPC_C_No_Silk	100nF_10V	1	CD603C10K9RAC TU	100nf	10%	10V
Surf Mount Tantalum Capacitor 47uf, 10V, ± 20%, 55°C -15°C, 125°C, 1.06g [3216 12Metric]		CAP POL_1206_3216- MFG	47uF_10V	1	TCTAL1A476MBR	47uf	20%	10V
Multilayer Ceramic Capacitor, 4.7uF, 10V, ± 10%, X5R, 0603 [1608 Metric]	C2C, C4C	CD603-IPC_C_No_Silk	4.7uF_10V	2	CL10A475KP8NN C	4.7uF	10%	10V
GRM188R61A26M01 Capacitor, 22uf, 10V, ± 20%, X5R, 0603 [1608 Metric]	C2L	CD603-IPC_C_No_Silk	22uF_10V	1	GRM188R61A26- M15D	22uf	20%	10V
T491A476M006AT Capacitor, 4.7uF, 10V, ± 20%, T491 Series	C4L	CAP POL_1206_3216- MFG	47uF_6_3V	1	T491A476M006AT	47uf		
GRM188R60J22M0A0 Capacitor, 22uf, 6.3V ± 20%, X5R, 0603 [1608 Metric]	C5L, C6L	CD603-IPC_C_No_Silk	22uF_6_3V	1	GRM188R60J22M0A 0AD	22uf	20%	6.3V
CD50T23-SRV05-4 VS-2020E 5V 15W SOT223	D1C, D1F, D2C	SOT23-6-IPC_C	SRV05-4	3	CD50T23-SRV05-4			
YELLOW SMD	D1L	LED_0603_YELLOW	LED_0603_YELLOW	1				
F0603 Fuse PPTC SMD 0603	F1P, F1U	RO603-IPC_C	FUSE_PPTC_0603	2		500mA, 300mA		
3.2mm	H1H, H2H, H3H, H4H	MountingHole_3.2m m_M2_Pad_Via_Max	MountingHole_Pad_3 2mm	4		3.2mm		
ESPB266-ESP-12-F	I1C1E	ESPB266-ESP-12-Large	ESPB266-ESP-12-F	1				
217175-0001 Connector, IEC Type C Female, crimpable, 0.5mm Right Angle SMT Embossed T/R, Tape and Reel	J1C	USB-Type-C-6-Pin- SMT	USB-Type-C-6-Pin- SMT	1				
ZK05	J1F, J2F	Front_Panel_2x05_P 2.54mm_Horizontal 2.54mm	Front_Panel_2x05_P	2				
ZK04	J1I	PinHeader_2x04_P2.5 4mm_Vertical	P2C_2x04_P2.54mm	1				
Tk06	J1U	PinHeader_1x06_P2.5 4mm_Vertical_No.3 3	JART_1x06_P2.54mm 3	1				
2.54 Pitch	J2C, J3C	USB_Front_Panel_2 x05_P2.54mm_Hori- zontal_Right	USB_Front_Panel_2 x05_P2.54mm	2				
BSS138NH6327 Single N-Channel 60 V 3.5 Ohm 1 nC SiPMOS® Small Signal Mosfet -SOT-23	Q1M, Q2M, Q3M	SOT-23-3-IPC_C	BSS138NH6327	3	BSS138NH6327			
PMPB140PZ	D1P, Q2P	BRN2030M-MFG	PMPB140PZ	2	PMPB140PZ			
RCW0603SK10FK SMD Chip Resistor, 100 Ohm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1C, R2C	RO603-MFG	5.1K	2	RCW0603SK10F EA	5.1K	1%	75V
RC0603FR-0710KL SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1E, R1L, R2E, R2L, R4E, R4M, R5E, R5M, R6M, R7M	RO603-MFG	10K	10	RC0603FR-0710KL	10K	1%	75V
RC0603FR-072K2L SMD Chip Resistor, 100 Ohm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1I, R2I	RO603-MFG	2.2K	2	RC0603FR-072K2L	2.2K	1%	50V
RC0603FR-101KL SMD Chip Resistor, 1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R1K, R4K	RO603-MFG	1K	2	RC0603FR-101KL	1K	1%	50V
AC0603FR-07100R SMD Chip Resistor, 100 Ohm, ± 1%, 100 mW, 0603 [1608 Metric], Thin Film, General Purpose	R1M, R2M, R3M	RO603-MFG	100R	3	AC0603FR- 07100R	100R	1%	50V
AC0603FR-07100KL SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thin Film, General Purpose	R1P, R2P	RO603-MFG	100K	2	AC0603FR- 07100KL	100R	1%	50V
RC0603JR-070R Zero Ohm Resistor Jumper, 0603 [1608 Metric], Thick Film, 100mW, 1A, Surface Mount	R2K, R3C	RO603-MFG	0R	2	RC0603JR-070R	0mR	1%	50V
MC03E2ZPFX1691 Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 0.1PPM	R2L	RO603-MFG	1.69K	1	MC03E2ZPFX1691	1.69K	1%	
ERJ-3EKF3302V 0.1W 10% 100ppm/C Pad SMD Automotive 7/8	R3L	RO603-MFG	33K	1	ERJ-3EKF3302V	33K	1%	75V
CR0603-FX-2002LF SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose	R4L	RO603-MFG	20K	1	CR0603-FX- 2002LF	20K	1%	50V
Res Thick Film 0603 2.4K Ohm 1% 170mW ±10ppm/C Molded SMD SMD Paper 1/8	R5L	RO603-MFG	2.4K	1	MC03E2ZPFX2491	2.49K	1%	
UART_RX/TX Digital IC	RXTX1U	UART_RX_RX_0603	UART_RX_RX_0603	1		470R		
EVP-AWED4A 3.0mA 1.20mA/1.15mA 3.3N / 0.150mA ST	SW1K, SW2K	PANASONIC EVPWA	EVP-AWED4A	2				
SGM2019 LDO U-Reg Adj 0.1A SOT23-3	U1L	SOT23-3-IPC_A	SGM2019	1	SGM2019- ADJYN5G/TR			
ADJYN5G/TR MuModule 0.95V 1.6V Dual, 12V 2% 200 mW SMT 2-Pin SOD- 323 / ON Semiconductor								
MM3212VST1G MM3212VST1G	TD1P, TD2P	SOD-323	MM3212VST1G	2	MM3212VST1G		2%	

Design Rules Verification Report

Filename : C:\Users\desktop\Documents\Project Files\Altium\Projects\Project - Development\ESP8266-Deskop_Power\ESP8266-Deskop_Power.Pc Warnings 0
Rule Violations 0

Warnings
Total 0

Rule Violations	
Clearance Constraint (Gap=4mm) (InNetClass('PowerRails_HighVoltage_AC') Or	0
Clearance Constraint (Gap=0.254mm) (InComponentClass('Via_Plugged')), (IsPad)	0
Clearance Constraint (Gap=0.254mm) (All), (All)	0
Short-Circuit Constraint (Allowed=No) (All), (not IsBoardCutoutRegion)	0
Un-Routed Net Constraint (All)	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.18mm) (Max =0.4mm) (Preferred=0.254mm) (InNetClass('Power_Signal'))	0
Width Constraint (Min=0.2mm) (Max =25.4mm) (Preferred=0.3mm) (InNetClass('PowerRails_LowVoltage_DC'))	0
Width Constraint (Min=0.2mm) (Max =25.4mm) (Preferred=0.3mm) (InNetClass('GND'))	0
Width Constraint (Min=0.11mm) (Max =0.11mm) (Preferred=0.11mm) (InNetClass('Signal'))	0
Width Constraint (Min=0.303mm) (Max =0.303mm) (Preferred=0.303mm) (InNetClass('Signal_50_ohm'))	0
Routing Layers(All)	0
Routing Via (MinHoleWidth=0.3mm) (Max HoleWidth=0.5mm) (PreferredHoleWidth=0.3mm) (MinWidth=0.45mm)	0
Differential Pairs Uncoupled Length using the Gap Constraints (Min=0.127mm) (Max =0.127mm) (Preferred=0.127mm)	0
Differential Pairs Uncoupled Length using the Gap Constraints (Min=0.381mm) (Max =0.381mm) (Preferred=0.381mm)	0
Differential Pairs Uncoupled Length using the Gap Constraints (Min=0.381mm) (Max =0.381mm) (Preferred=0.381mm)	0
SMD To Corner (Distance=0.127mm) (All)	0
SMD Neck-Down Constraint (Percent=90%) (not IsTestpoint)	0
SMD Entry (Side = Allowed) (Corner = Allowed) (Any Angle = Not Allowed) (Ignore First Corner = Allowed)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Minimum Annular Ring (Minimum=0.2mm) (IsThruPin)	0
Minimum Annular Ring (Minimum=0.075mm) (IsVia)	0
Acute Angle Constraint [Tracks Only] (Minimum=60.000) (All)	0
Hole Size Constraint (Min=0.3mm) (Max =6.3mm) (All)	0
Pads and Vias to follow the Drill pairs settings	0
Hole To Hole Clearance (Gap=0.45mm) (ispad),(IsPad)	0
Minimum Solder Mask Sliver (Gap=0.13mm) (All), (All)	0
Silk To Solder Mask (Clearance=0.15mm) (All), (All)	0
Silk to Silk (Clearance=0.102mm) (All), (All)	0
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) ((OnLayer('Top Layer') OR OnLayer('Bottom Layer')))	0
Height Constraint (Min=0mm) (Max =1816.048mm) (Preferred=12.7mm) (All)	0
Total	0

Electrical Rules Check Report

Class	Document	Message
		Successful Compile for ESP8266-Desktop_Power.PnjPcb

Different Descriptions
Schematic Object

MM3Z12VST1G Zener Diode, 12V 2% 200 mW SMT 2-Pin SOD-323

MM3Z12VST1G Zener Diode, 12V 2% 200 mW SMT 2-Pin SOD-323

PCB Object

ON Semiconductor MM3Z12VST1G [ZD1P]

ON Semiconductor MM3Z12VST1G [ZD2P]